Training Course of SOC Encounter

REF:
- CIC Training Manual – Cell-Based IC Physical Design and Verification with SOC Encounter, July, 2006
- CIC Training Manual – Mixed-Signal IC Design Concepts, July, 2007

Speaker: K. –T. Wu

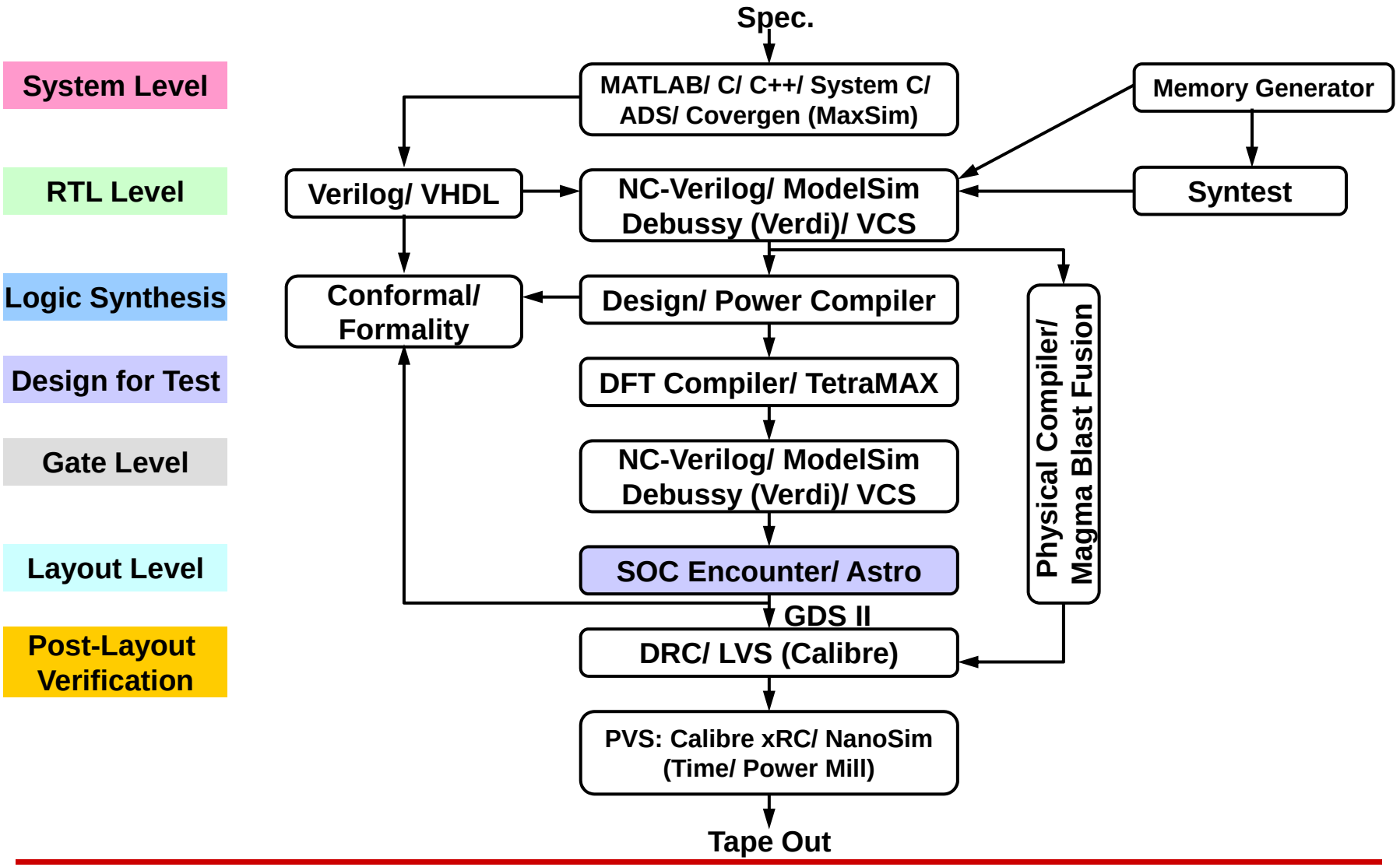
ARES Lab.
Advanced REliable System Lab

Outline

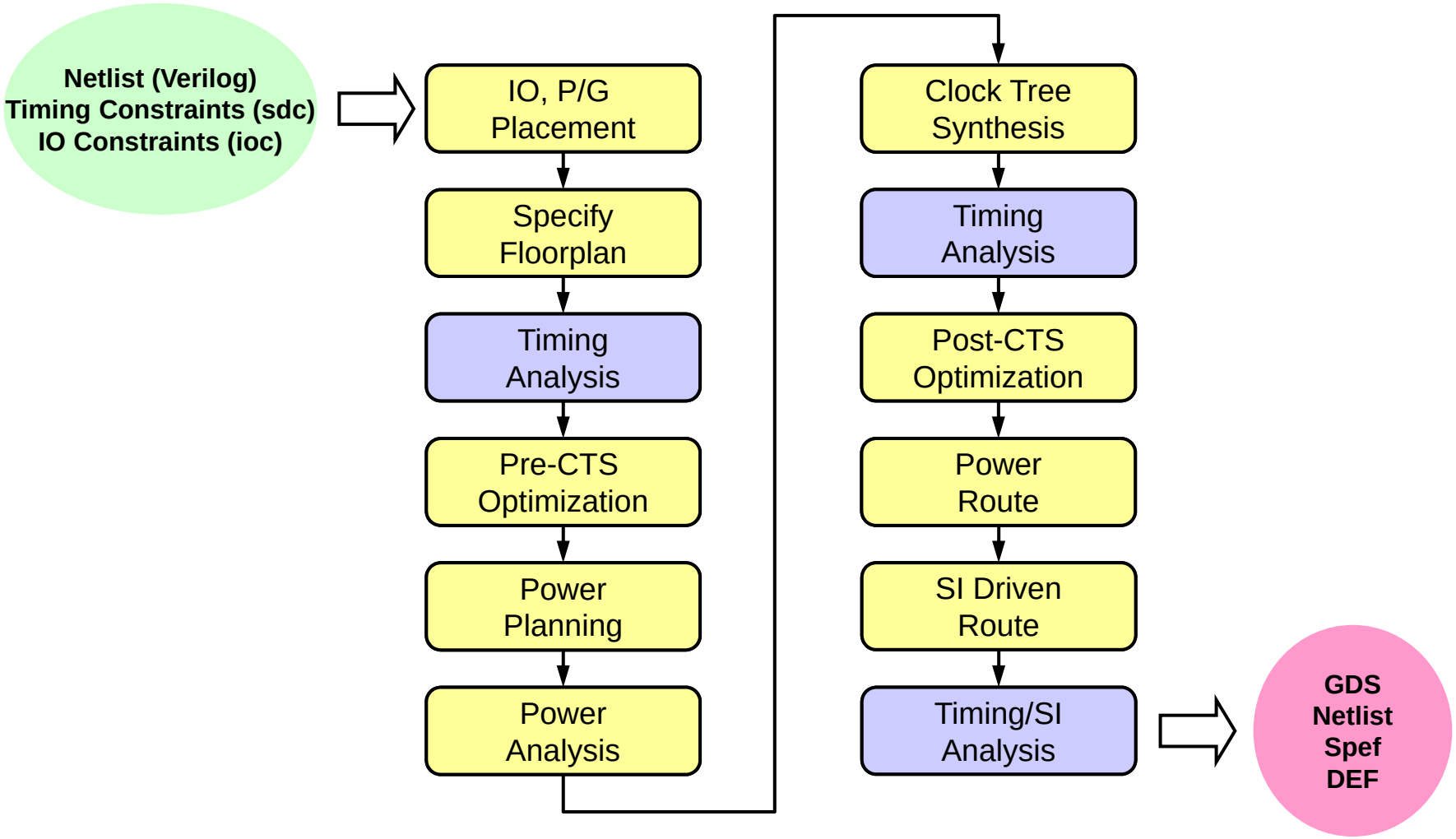
- Basic Concept of the Placement & Routing
- Auto Place and Route Using SOC Encounter
- LAB

BASIC CONCEPT OF THE PLACEMENT & ROUTING

Cell-Based Design Flow

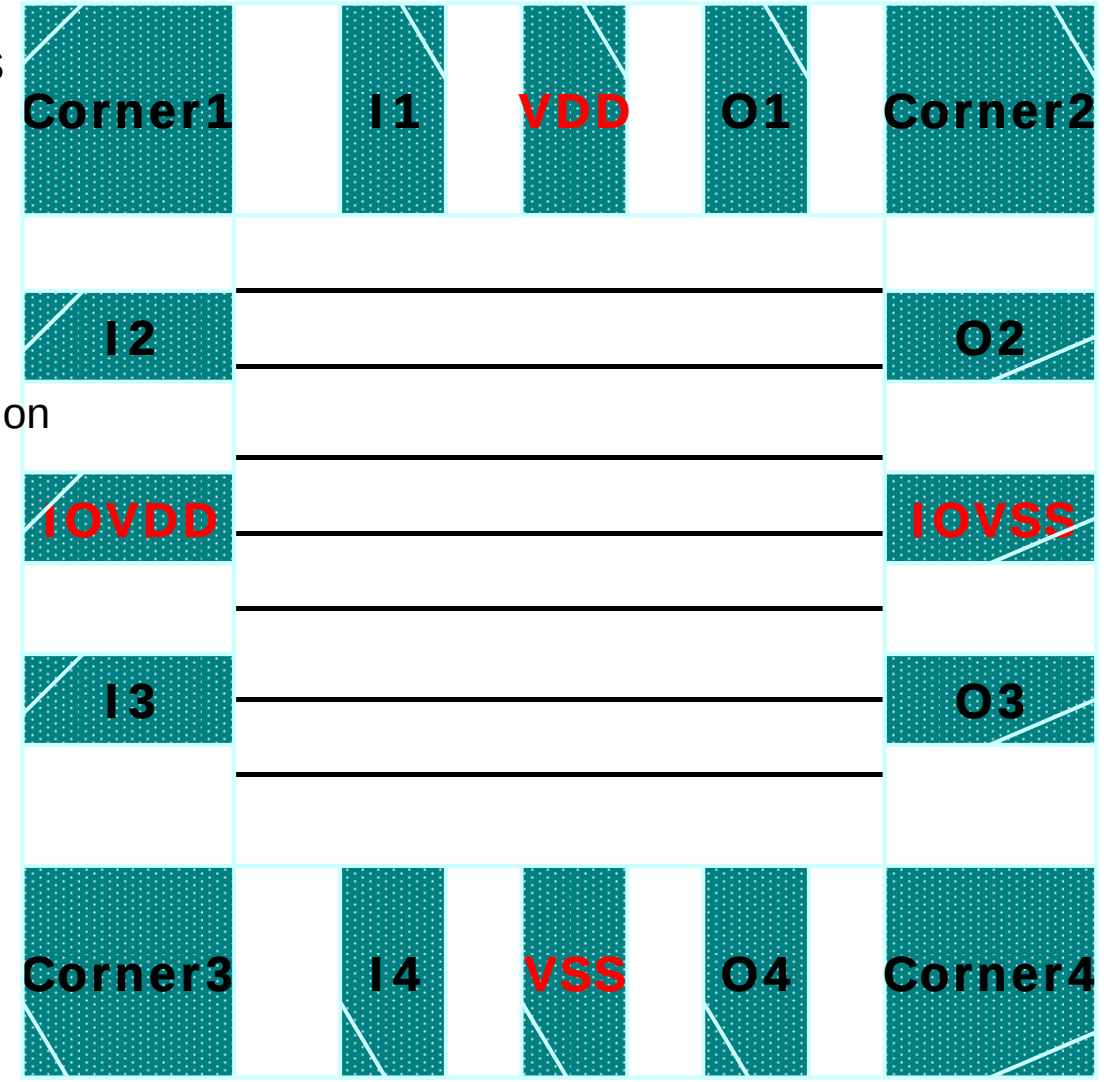


SOC Encounter P&R Flow



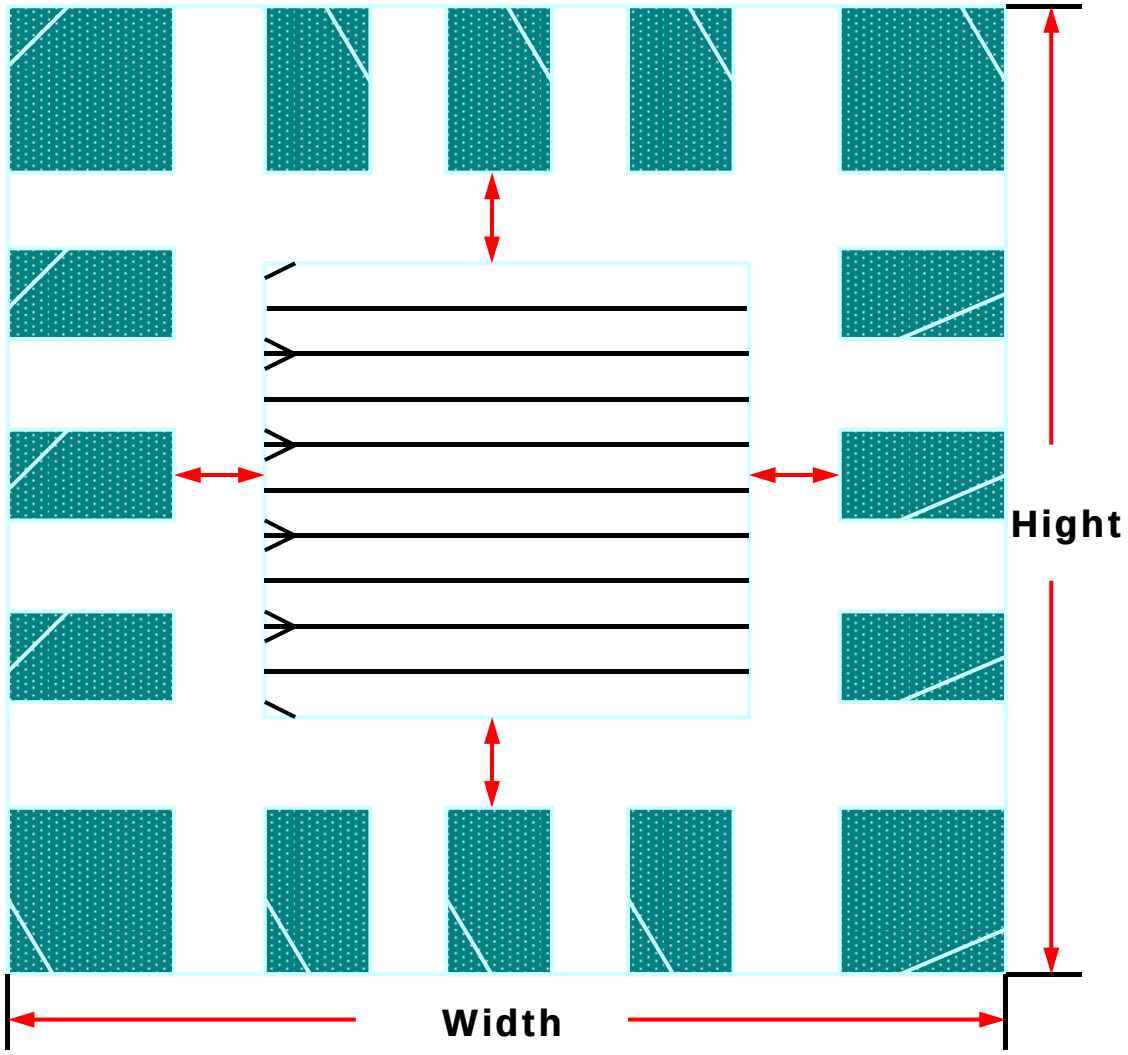
IO, Power/Ground Placement

- Determine the positions of the PADs
  - Functional IO PAD
  - Power/Ground PAD
  - Corner PAD
    - Just for the connection of PAD power rings



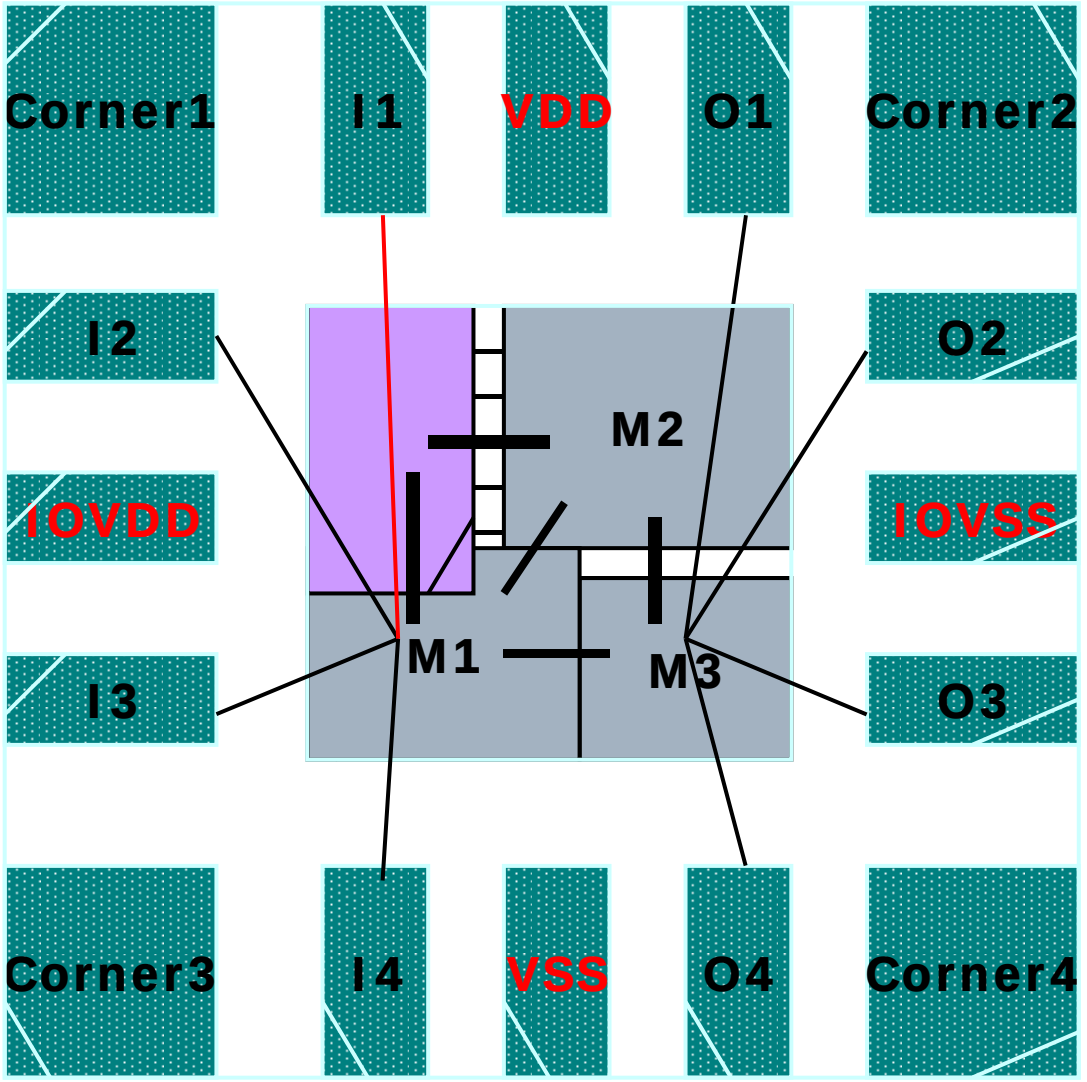
Specify Floorplan

- Determine the aspect ratio of the Core
- Determine the gap between the PAD and Core
  - The Core Utilization is determined in this step
  - The final CHIP area is almost determined in this step



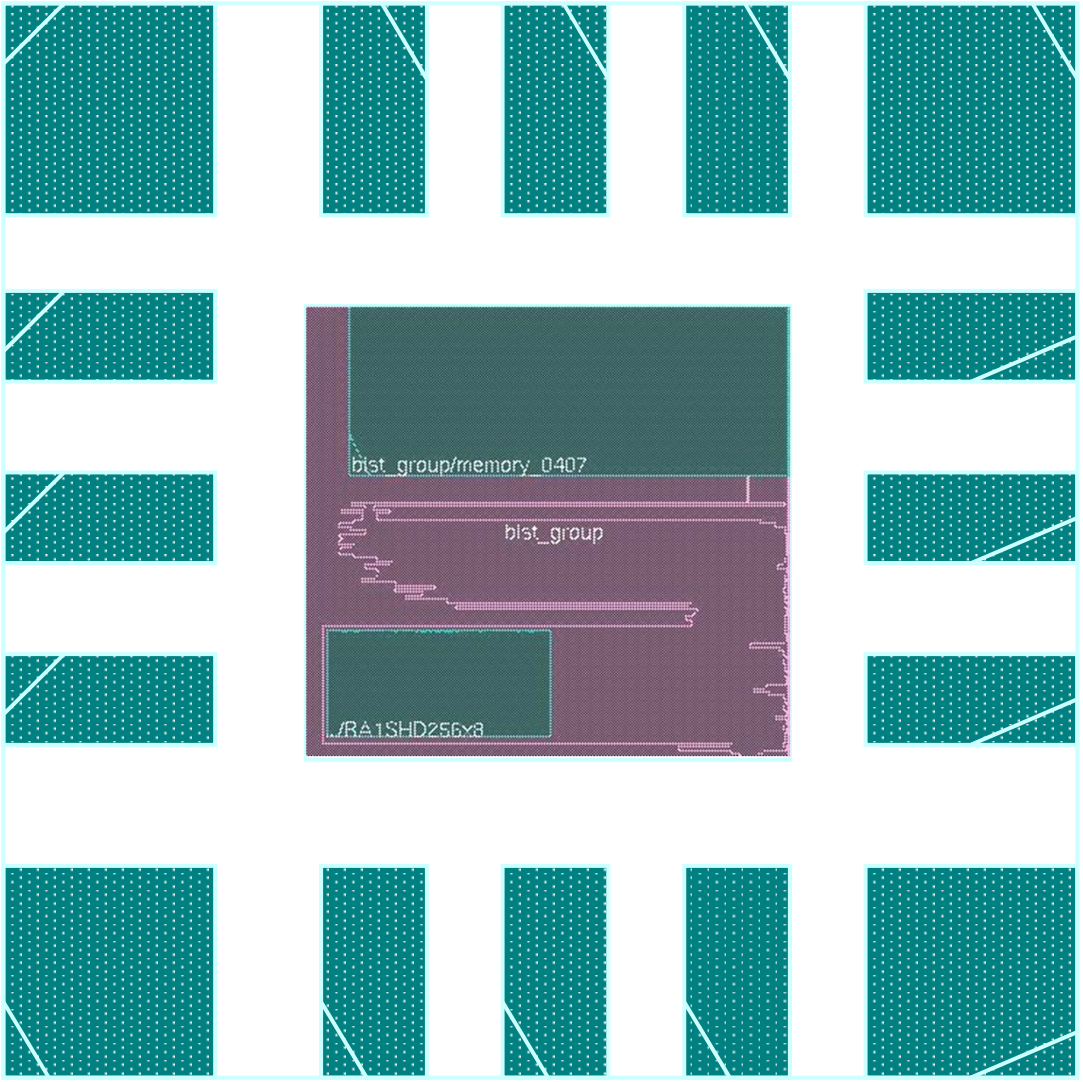
Floorplan

- Determine the related positions of Hard Blocks
  - The performance is highly affected



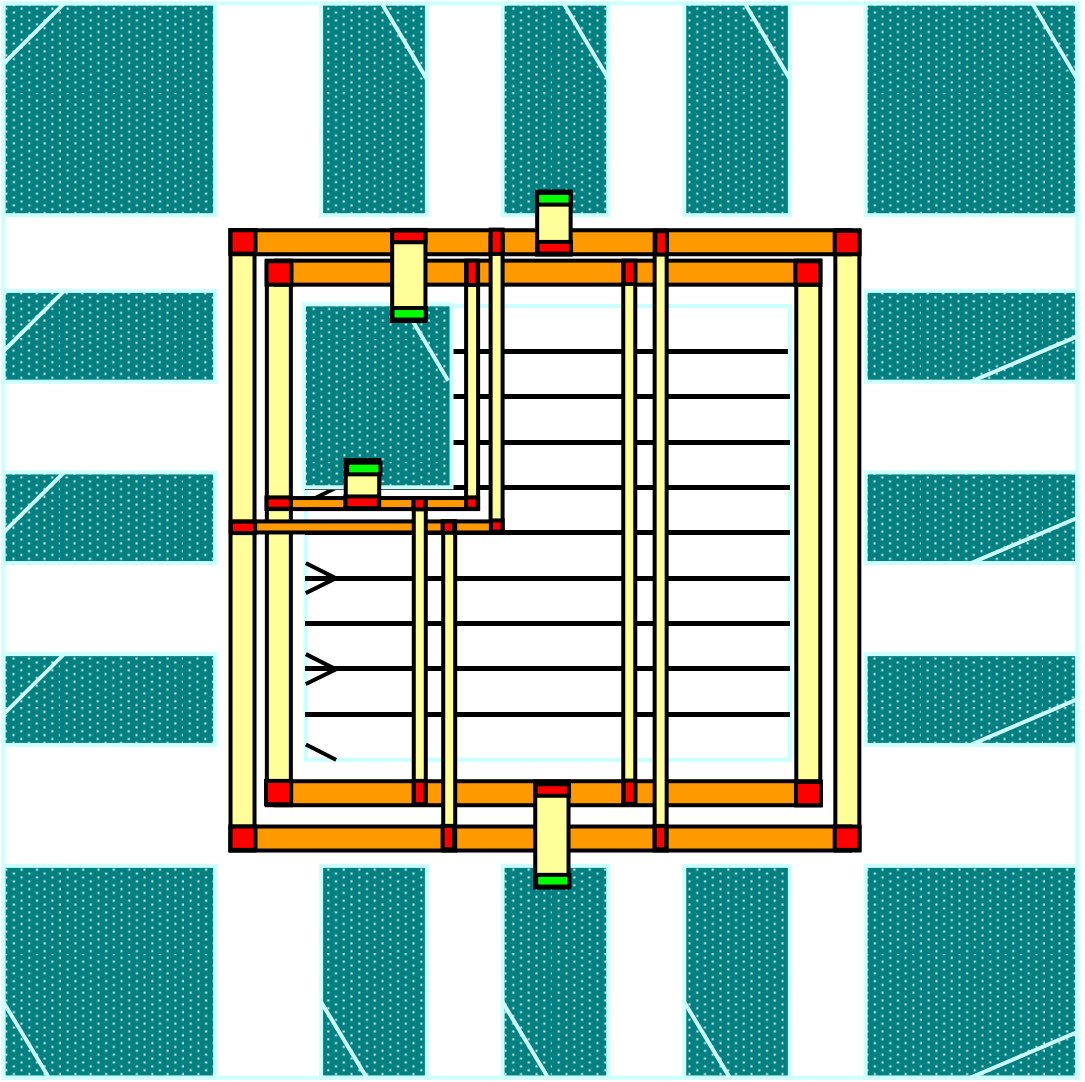
Amoeba Placement

- Observe the result of cells and Hard Blocks placement

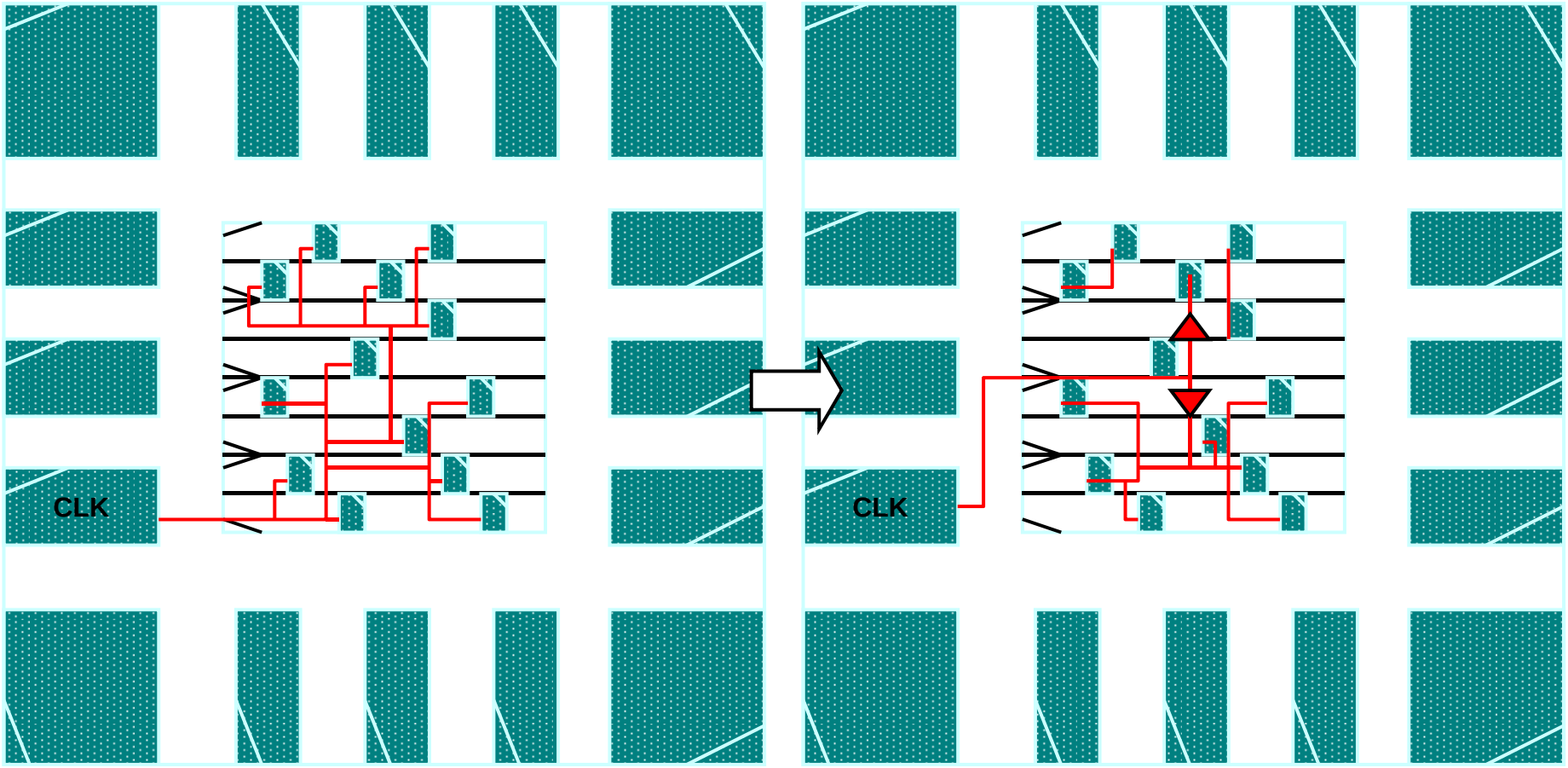


Power Planning

- Plan the power ring & power stripe
  - IR-drop consideration

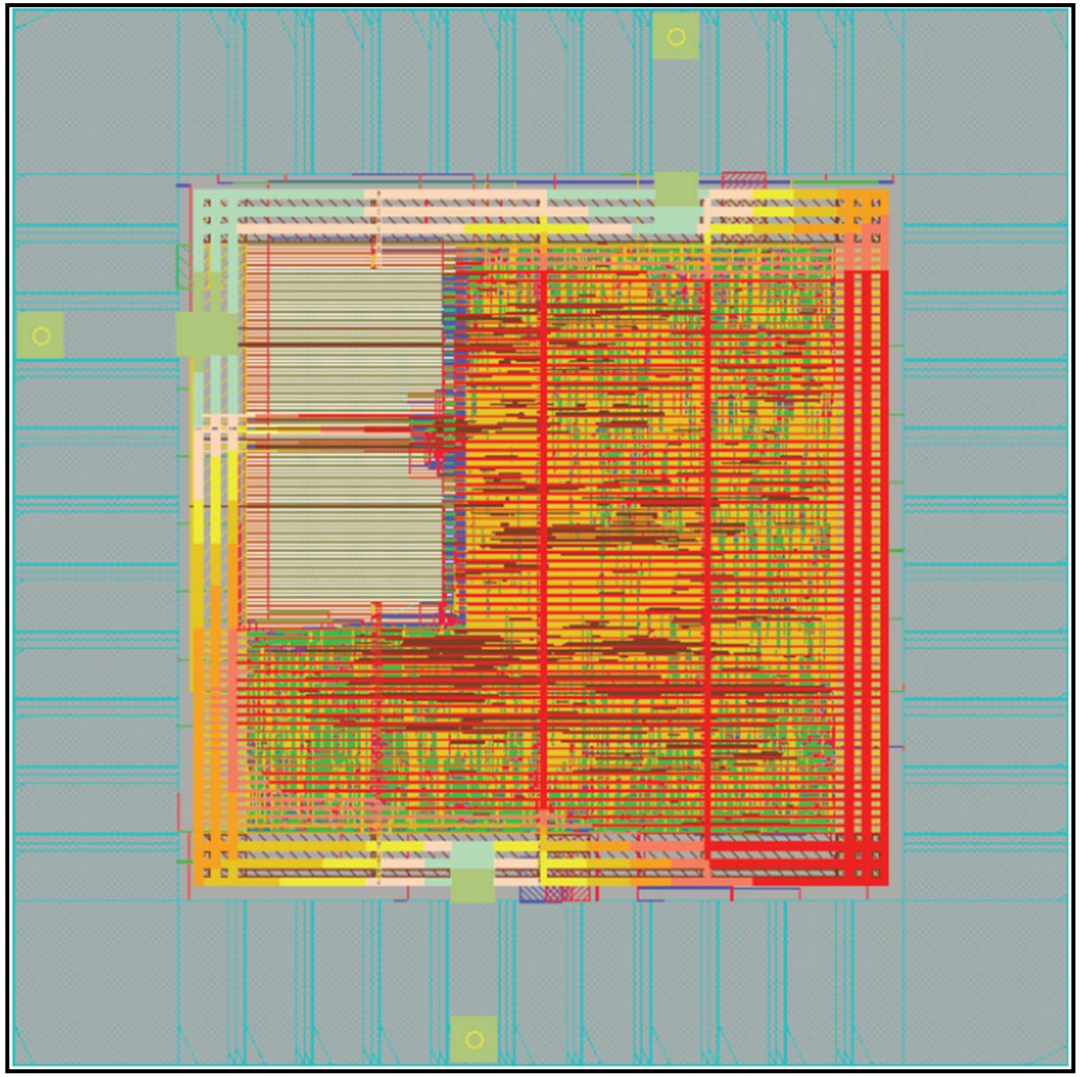


Clock Tree Synthesis



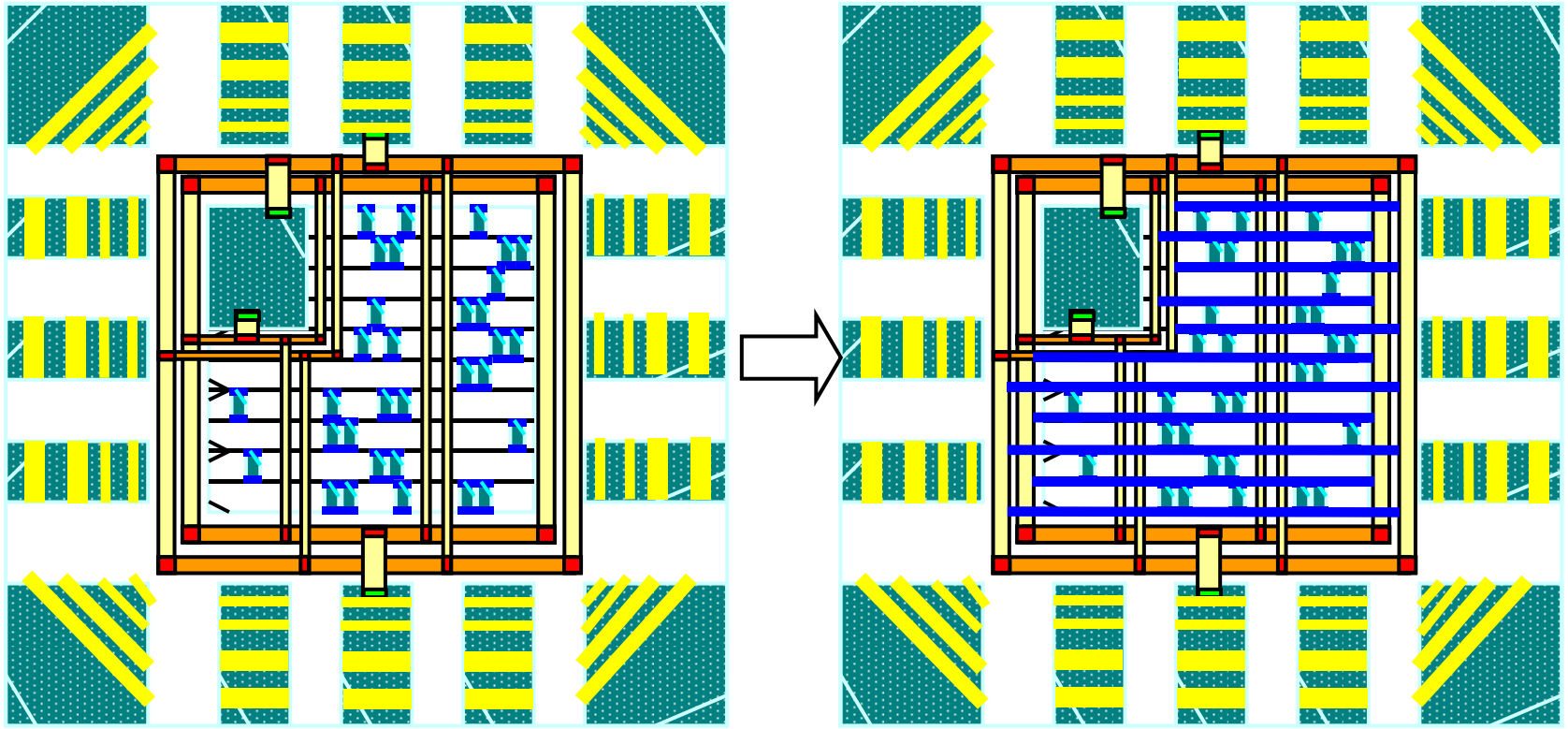
Power Analysis

- IR-drop & electron migration



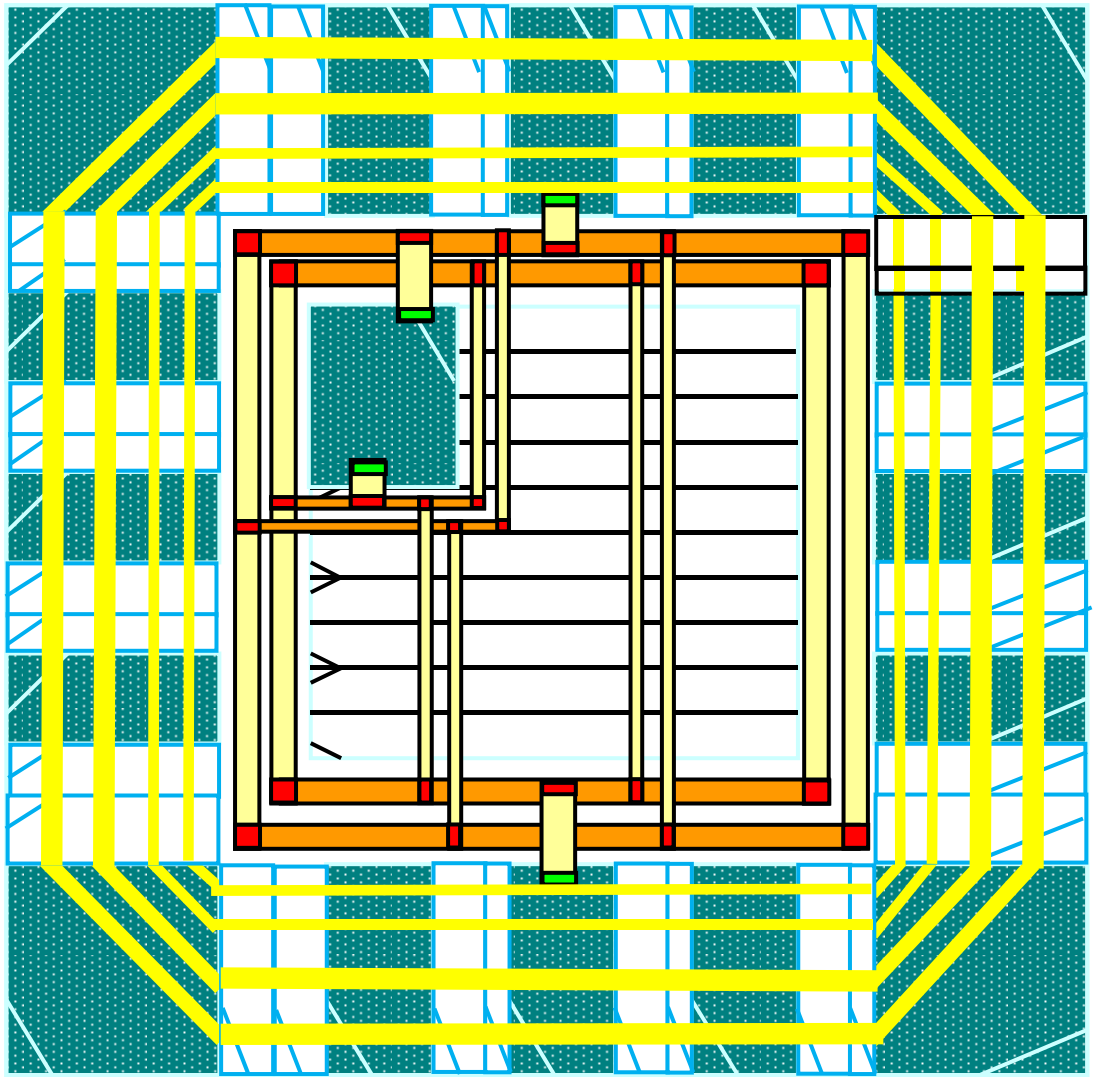
Power Route

- Connect the power pins of standard cells to the global power lines



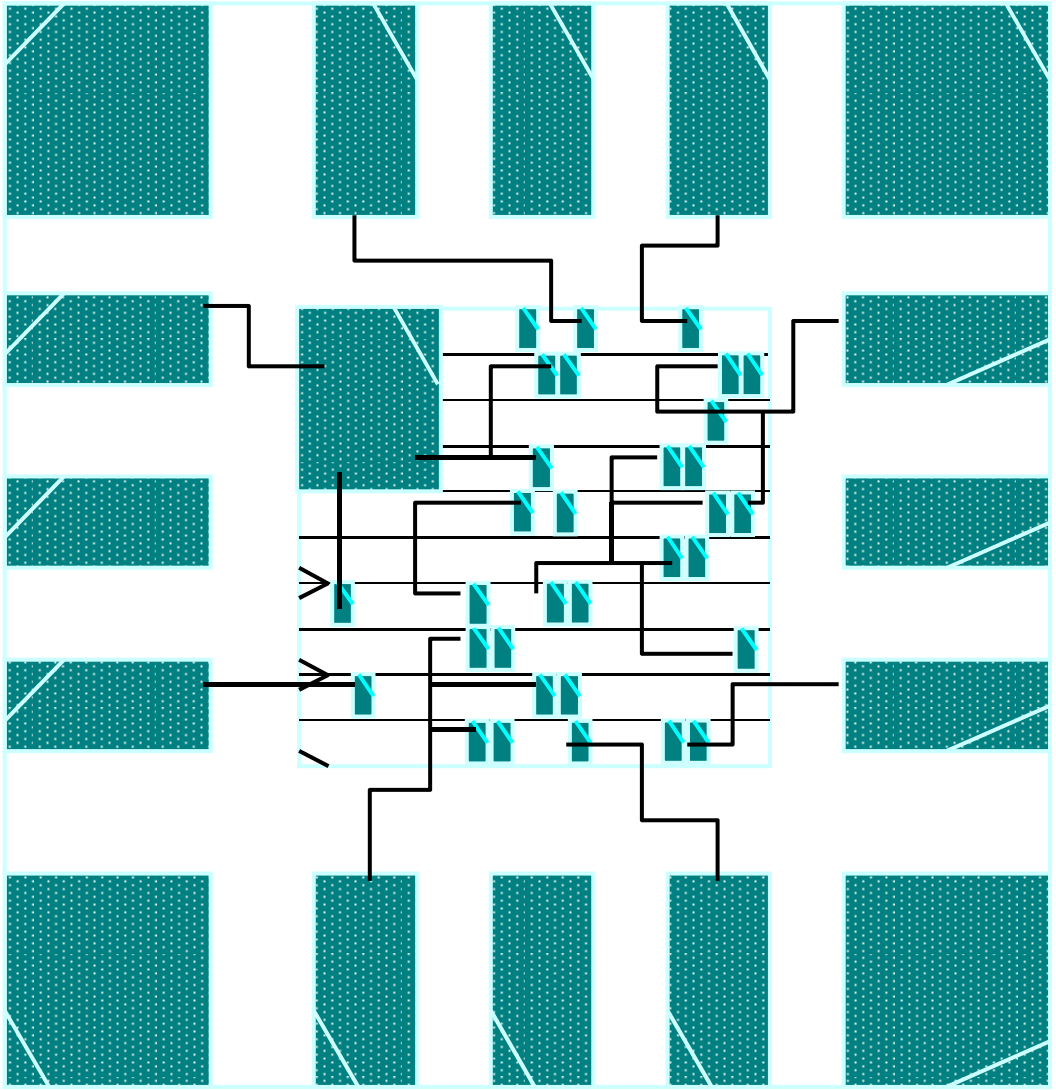
Add IO Filler

- Fill the gap between PADs
  - Connect the PAD power rings



Routing

- Construct the final interconnections



Prepare Data

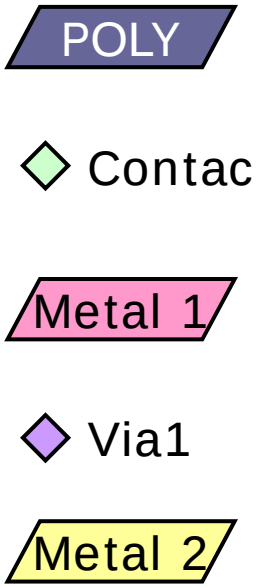
- Library
  - Physical Library (LEF)
    - Information of technology, standard cells, Hard Blocks, and APR
  - Timing Library (LIB)
    - Timing information of the standard cells and Hard Blocks
  - Capacitance Table
    - For more accurate RC analysis
  - Celtic Library
    - For crosstalk analysis
  - FireIce/Voltage Storm Library
    - For RC extraction and power analysis

Not Necessary !

- User Data
  - Gate-Level Netlist (Verilog)
  - SDC Constraint (*.sdc)
  - IO Constraint (*.ioc)

LEF Format – Process Technology

Layers



Design Rule

Net Width
Net Spacing
Area
Enclosure
Wide Metal Slot
Antenna
Current Density

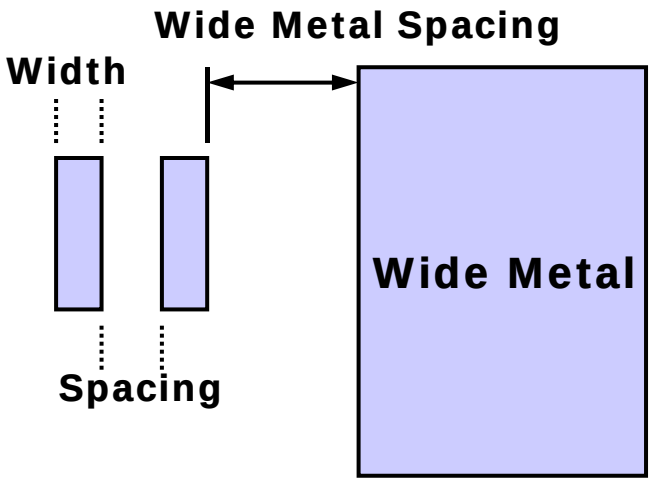
Parasitic

Resistance
Capacitance

LEF Format – Process Technology

Layer Define

```
Layer Metal1
  TYPE ROUTING;
  WIDTH 0.28;
  MAXWIDTH 8;
  AREA 0.202;
  SPACING 0.28;
  SPACING 0.6 RANGE 10.0 10000.0;
  PITCH 0.66;
  DIRECTION VERTICAL;
  THICKNESS 0.26;
  ANTENNACUMDIFFAREARATIO 5496;
  RESISTANCE RPERSQ 1.0e-01;
  CAPACITANCE CPERSQDIST 1.11e-04;
  EDGECAPACITANCE 9.1e-05;
END Metal1
```

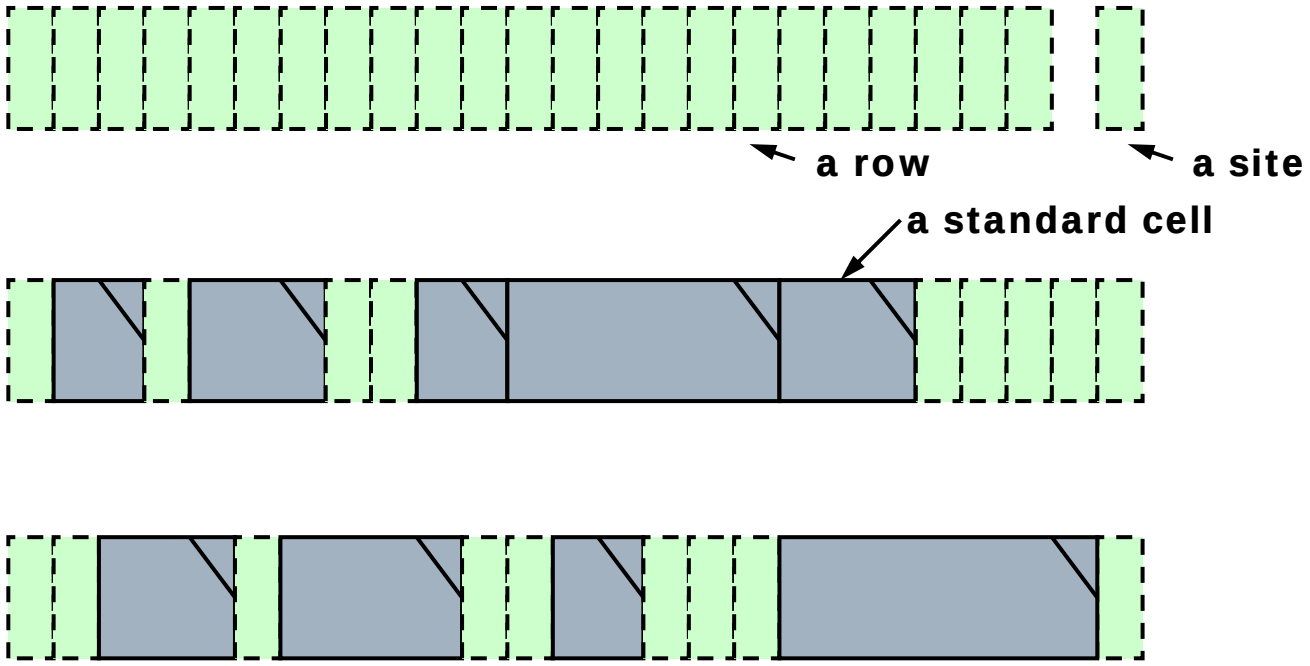


LEF Format – APR Technology

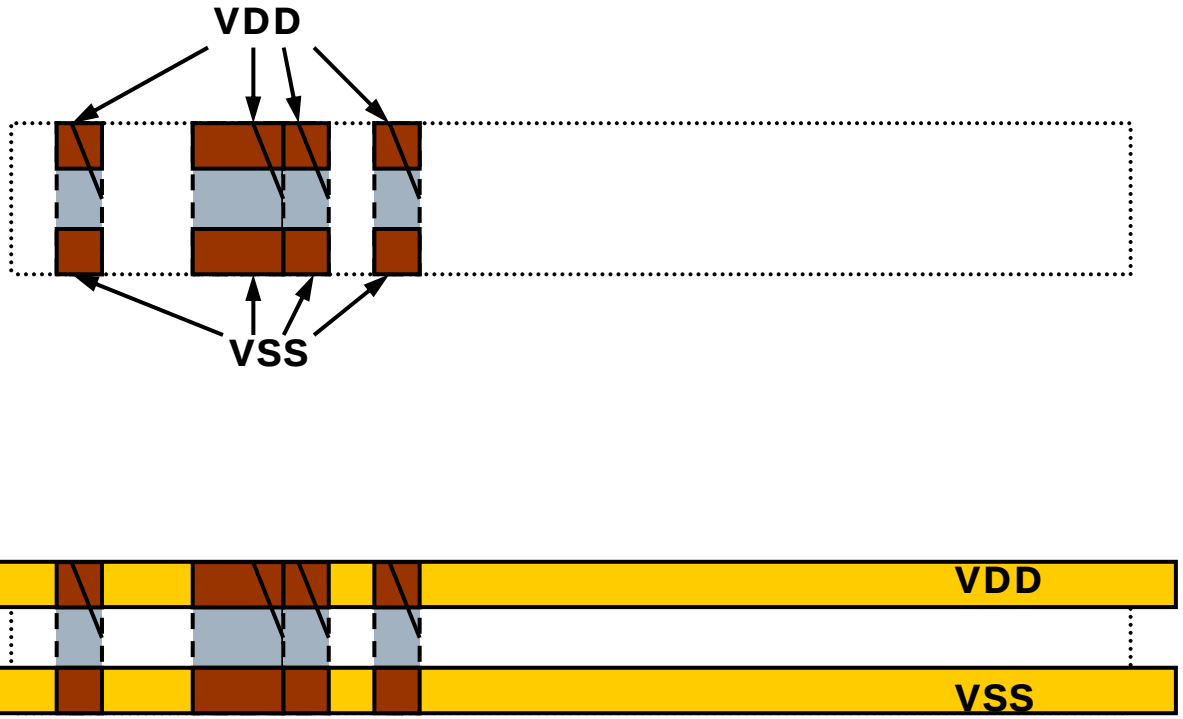
- Unit
- Site
- Routing Pitch
- Default Direction
- Via Rule

LEF Format – APR Technology

- Site
  - The placement site gives the placement grid of a family of macros

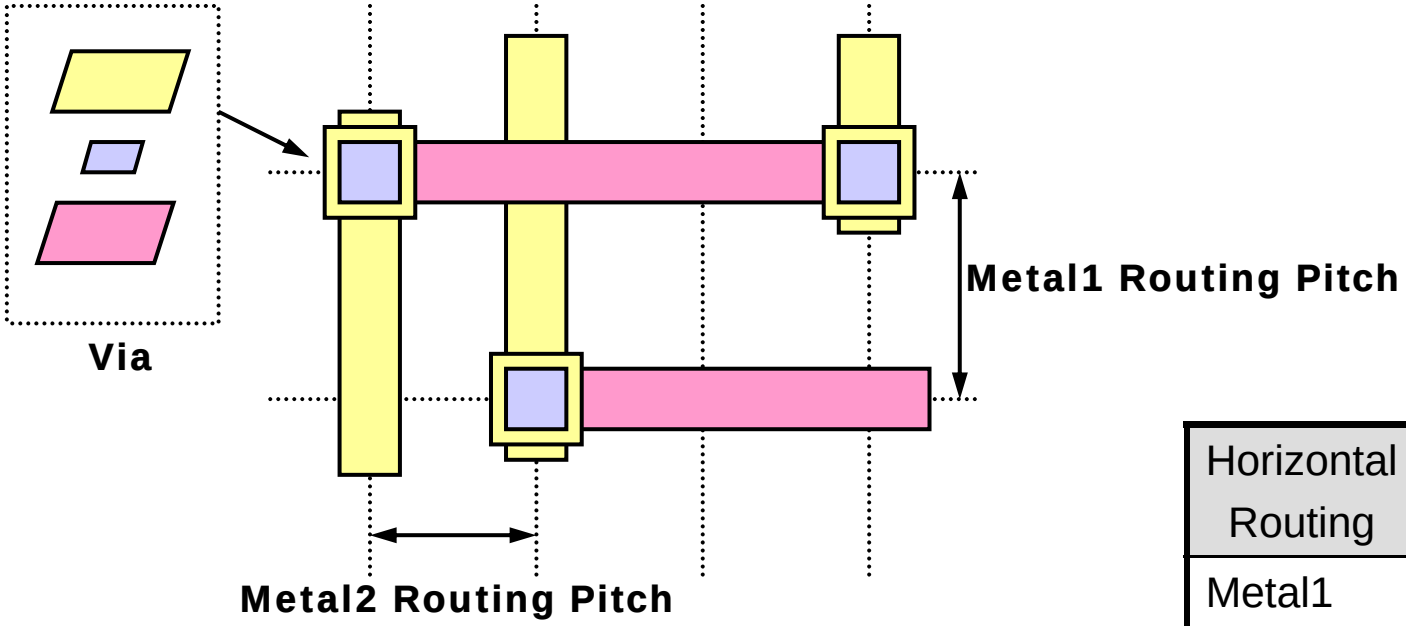


Row Based PR



LEF Format – APR Technology

- Routing Pitch
- Default Direction

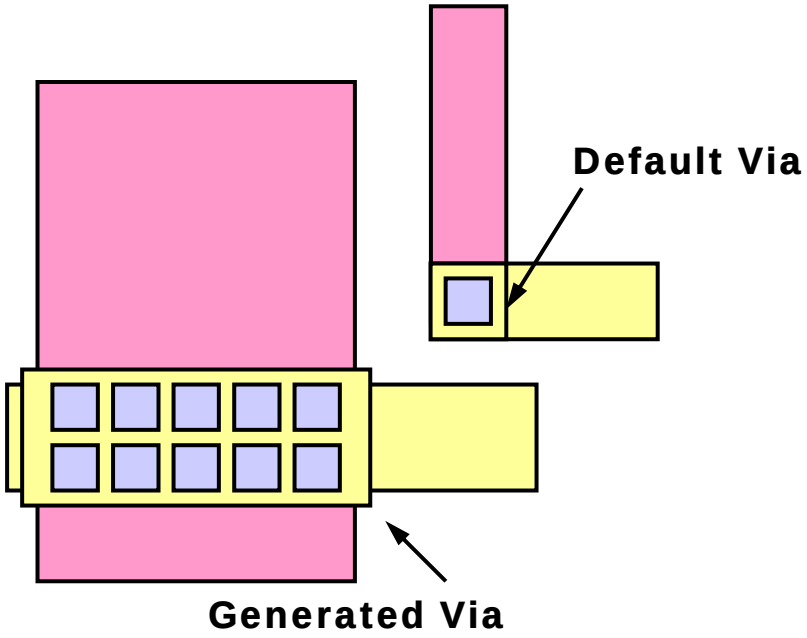


Horizontal Routing	Vertical Routing
Metal1	Metal2
Metal3	Metal4
Metal5	Metal6

LEF Format – APR Technology

- Via Generation
  - To connect the wide metal, a via array is generated to reduce the via resistance
  - Formulas for generating via arrays are defined

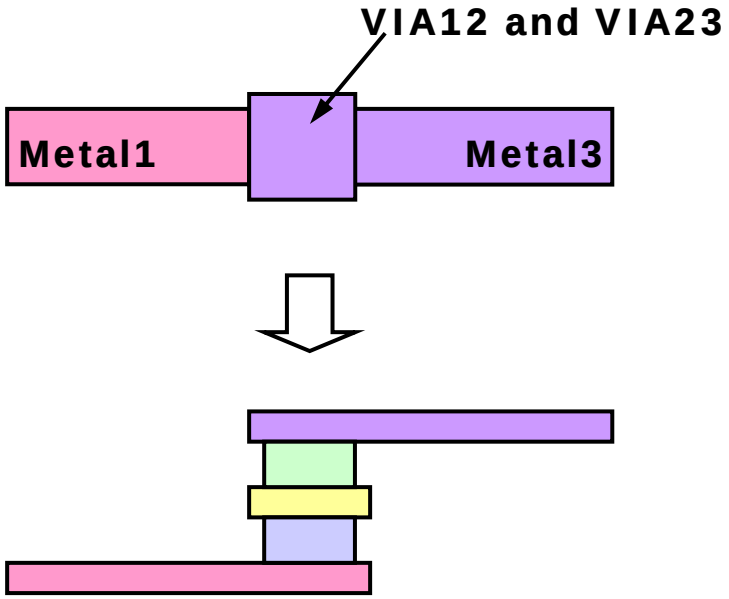
```
Layer Metal1
  Direction HORIZONTAL
  OVERHANG 0.2
Layer Metal2
  Direction VERTICAL
  OVERHANG 0.2
Layer Via1
  RECT -0.14 -0.14 0.14 0.14
  SPACING 0.56 BY 0.56
```



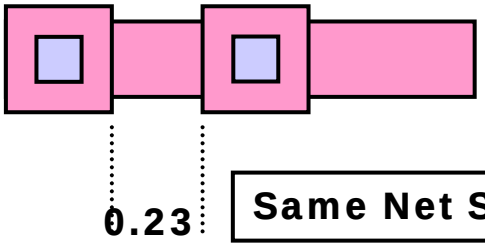
LEF Format – APR Technology

- Same Net Spacing

```
SPACING
  SAMENET Metal1 Metal1 0.23;
  SAMENET Metal2 Metal2 0.28 STACK;
  SAMENET Metal3 Metal3 0.28;
  SAMENET VIA12 VIA12 0.26;
  SAMENET VIA23 VIA23 0.26;
  SAMENET VIA12 VIA23 0.0 STACK;
END SPACING
```



VIA12 and VIA23 allow stack



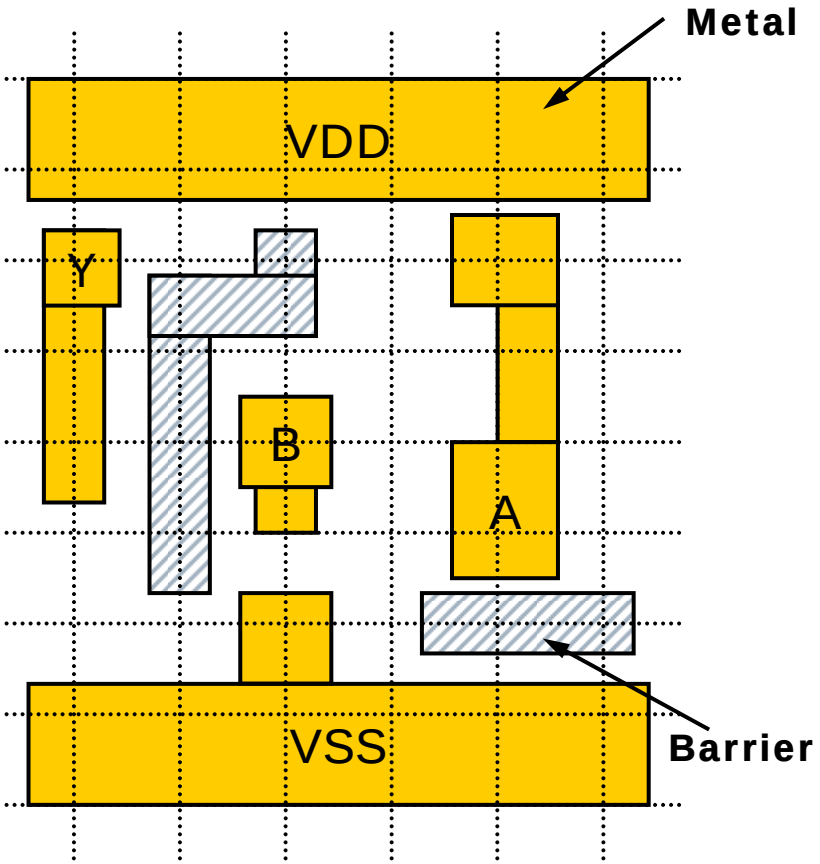
Same Net Spacing Rule

LEF Format – APR Technology

- Physical Macros
  - Define physical data for
    - Standard cells
    - I/O pads
    - Memories
    - Other hard macros
  - Describe abstract shape
    - Size
    - Class
    - Pins
    - Obstructions

LEF Format – APR Technology

- Physical Macros




```
MACRO ADD1
  CLASS CORE;
  FOREIGN ADD1 0.0 0.0;
  ORIGEN 0.0 0.0;
  LEQ ADD;
  SIZE 19.8 BY 6.4;
  SYMMETRY x y;
  SITE coresite;
  PIN A
    DIRECTION INPUT;
    PORT
    LAYER Metal1;
    RECT 19.2 8.2 19.5 10.3;
    ....
    END
  END A
....
END ADD1
```

LIB Format

- Operating condition
  - Slow, fast, typical
- Pin type
  - Input/output/inout
  - Function
  - Data/clock
  - Capacitance
- Path delay
- Timing constraint
  - Setup, hold, mpwh, mpwl, recovery

Gate-Level Netlist

- If designing a chip, IO PADs, power PADs, and Corner PADs should be added before the netlist is imported
- Make sure that there is no “assign” statement and no “*cell*” cell name in the netlist

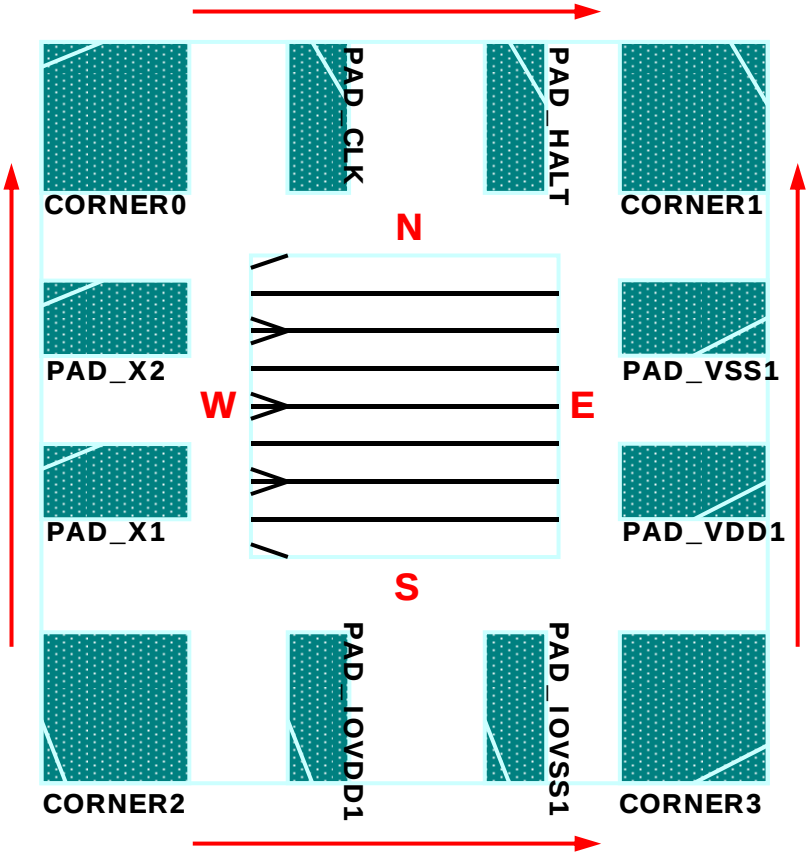
SDC Constraint

- Clock constraints
- Input delay/ Input drive
- Output delay/ Output load
- False path
- Multi-cycle path

IO Constraint

```
Version: 1
Pad: CORNER0          NW PCORNERDGZ
Pad: PAD_CLK          N
Pad: PAD_HALT         N

Pad: CORNER1          NE PCORNERDGZ
Pad: PAD_X1           W
Pad: PAD_X2           W

Pad: CORNER2          SW PCORNERDGZ
Pad: PAD_IOVDD1       S PVDD2DGZ
Pad: PAD_IOVSS1       S PVSS2DGZ

Pad: CORNER3          SE PCORNERDGZ
Pad: PAD_VDD1         E PVDD1DGZ
Pad: PAD_VSS1         E PVSS1DGZ
```

(*.ioc File)



Decide the NO. of Power/Ground PADs

- The following factors are considered:
  - SSO: Simultaneously Switch Outputs
  - SSN: The noise produced by SSO buffers
  - DI: Maximum NO. of copies for one specific kind of IO PAD switching from high to low simultaneously without making ground voltage level higher than 0.8 volt for one ground PAD
  - DF: Driving Factor, DF = 1/DI
  - SDF: Sum of Driving Factor
- Suggestion in SSO case:
  - Required NO. of ground PADs = SDF
  - Required NO. of power PADs = SDF/1.1

SDF Example

- If a design has 20 PDB02DGZ (2mA) and 10 PDD16DGZ (16mA). Then,
- SDF = 20 x 0.02 + 10 x 0.3 = 3.4
- In SSO case,
  - NO. of VSS PAD = 3.4 → 4
  - NO. of VDD PAD = 3.4/1.1 = 3.09 → 4

IO Type	2mA	4mA	8mA	12mA	16mA	24mA
DF Value	0.02	0.03	0.09	0.18	0.3	0.56

Tips to Reduce the Power/Ground Bounce

- Don’t use stronger output buffers than what is necessary
- Use slew-rate controlled outputs
- Place power pad near the middle of the output buffer
- Place noise sensitive I/O pads away from SSO I/Os
- Place VDD and VSS pads next to clock input buffer

AUTO PLACE AND ROUTE USING SOC ENCOUNTER

CHIP-Level Netlist

- If your gate-level netlist is generated by “CORE-level synthesis”
  - You should all the “CHIP-level module” in it

```
module CHIP ( I_clk, I_rst, I_ams, I_CSI, I_finj, I_si, I_se, I_scantest,
        I_bist_mode, I_mem_sel, I_WEN_S, I_CS_S, I_OE_S, I_DI_S, I_ADDR_S,
        O_cmd_done, O_BGO, O_state_addr, O_hold_state_addr, O_so, O_Q, I_tpclk,
I_test_si2, O_test_so2 );
  input [1:0] I_finj;
  input [7:0] I_DI_S;
  input [7:0] I_ADDR_S;
  output [3:0] O_state_addr;
  output [3:0] O_hold_state_addr;
  output [7:0] O_Q;
  input I_clk, I_rst, I_ams, I_CSI, I_si, I_se, I_scantest, I_bist_mode,
        I_mem_sel, I_WEN_S, I_CS_S, I_OE_S,I_tpclk, I_test_si2;
  output O_cmd_done, O_BGO, O_so, O_test_so2;
  wire   clk, rst, ams, CSI, si, scantest, se, bist_mode, mem_sel, WEN_S, CS_S,
        OE_S, cmd_done, BGO, so;
  wire   [1:0] finj;
  wire   [7:0] DI_S;
  wire   [7:0] ADDR_S;
  wire   [3:0] state_addr;
  wire   [3:0] hold_state_addr;
  wire   [7:0] Q;

  bist_group bist_group ( .clk(clk), .rst(rst), .ams(ams), .CSI(CSI), .finj(
        finj), .si(si), .scantest(scantest), .se(se), .bist_mode(bist_mode),
        .mem_sel(mem_sel), .WEN_S(WEN_S), .CS_S(CS_S), .OE_S(OE_S), .DI_S(DI_S),
.ADDR_S(ADDR_S), .cmd_done(cmd_done), .BGO(BGO), .state_addr(state_addr),
        .hold_state_addr(hold_state_addr), .so(so), .Q(Q) , .tpclk(tpclk), .test_si2(test_si2),
.test_so2(test_so2));
  PDIDGZ PAD_clk ( .PAD(I_clk), .C(clk) );
  PDIDGZ PAD_rst ( .PAD(I_rst), .C(rst) );
  PDIDGZ PAD_ams ( .PAD(I_ams), .C(ams) );
```

CHIP-Level Netlist (Cont')

- If your design has a "Hard Block", you should add an "empty module" for it
  - The module name should be the same as the "cell name" of the Hard Block

```
module memory_0407 (O, clock, cen_in, oen_in, wen_in, A, D);
  input       clock;
  input [7:0] A;
  input [7:0] D;
  input       cen_in;
  input       oen_in;
  input       wen_in;
  output [7:0] O;
endmodule
```

(Module Declaration)

```
  wire  [7:0] D;
  wire  [7:0] DI_T;
  wire  [7:0] A;
  wire  [7:0] ADDR_T;
  wire  [7:0] Q2;
  wire  [7:0] Q1;

  RA1SHD256x8 RA1SHD256x8 ( .Q(Q1), .CLK(clk), .CEN(CEN1), .OEN(n168), .WEN(
      WEN), .A(A), .D(D) );

  memory_0407 memory_0407(.O(Q2), .clock(clk), .cen_in(CEN2), .oen_in(n168),
.wen_in(WEN), .A(A), .D(D));
```

(Module Reference)

Connected Wire Name in Verilog

Pin Name in SPICE

CHIP-Level Timing Constraint

Ex:

```
################################################

#  Created by Design Compiler write_sdc on Sun Jul 29 06:04:11 2007

################################################
set sdc_version 1.4

create_clock -period 9 -waveform {0 4.5} [get_ports {clk}]
set_input_delay 0.34 -clock "clk" [get_ports {ADDR_S[0]}]
set_input_delay 0.34 -clock "clk" [get_ports {ADDR_S[1]}]
set_input_delay 0.34 -clock "clk" [get_ports {ADDR_S[2]}]
set_input_delay 0.34 -clock "clk" [get_ports {ADDR_S[3]}]
set_input_delay 0.34 -clock "clk" [get_ports {ADDR_S[4]}]
set_input_delay 0.34 -clock "clk" [get_ports {ADDR_S[5]}]
set_input_delay 0.34 -clock "clk" [get_ports {ADDR_S[6]}]
set_input_delay 0.34 -clock "clk" [get_ports {ADDR_S[7]}]
set_input_delay 0.34 -clock "clk" [get_ports {DI_S[0]}]
set_input_delay 0.34 -clock "clk" [get_ports {DI_S[1]}]
set_input_delay 0.34 -clock "clk" [get_ports {DI_S[2]}]
set_input_delay 0.34 -clock "clk" [get_ports {DI_S[3]}]
```

CHIP-Level Clock Declaration

Set False Path to Your Test Pins

Set Parameters to the PAD IO

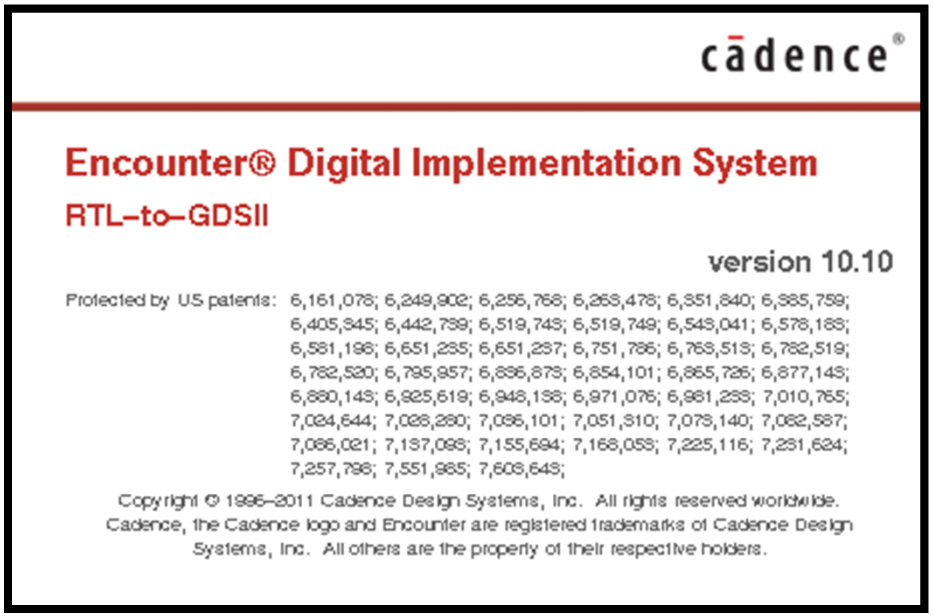
```
#  Created by Design Compiler write_sdc on Mon Jan  1 21:48:36 2007

################################################
set sdc_version 1.4
current_design CHIP
create_clock [get_pins {PAD_clk/C}] -name CLK1 -period 20 -waveform {0
10}

set_case_analysis 0 [get_ports {I_se}]
set_max_fanout 50 [current_design]
set_false_path  -from [get_ports {I_si}]
set_false_path  -from [get_ports {I_se}]
set_false_path  -from [get_ports {I_scantest}]

set_input_delay 0.34 -clock [get_clocks {CLK1}] [get_ports {I_ADDR_S[0]}]
set_input_delay 0.34 -clock [get_clocks {CLK1}] [get_ports {I_ADDR_S[1]}]
set_input_delay 0.34 -clock [get_clocks {CLK1}] [get_ports {I_ADDR_S[2]}]
set_input_delay 0.34 -clock [get_clocks {CLK1}] [get_ports {I_ADDR_S[3]}]
set_input_delay 0.34 -clock [get_clocks {CLK1}] [get_ports {I_ADDR_S[4]}]
set_input_delay 0.34 -clock [get_clocks {CLK1}] [get_ports {I_ADDR_S[5]}]
```

Getting Started

- *linux %>tcsh*
- *Before executing SOC encounter, please change your current location to your working folder “SOC”*

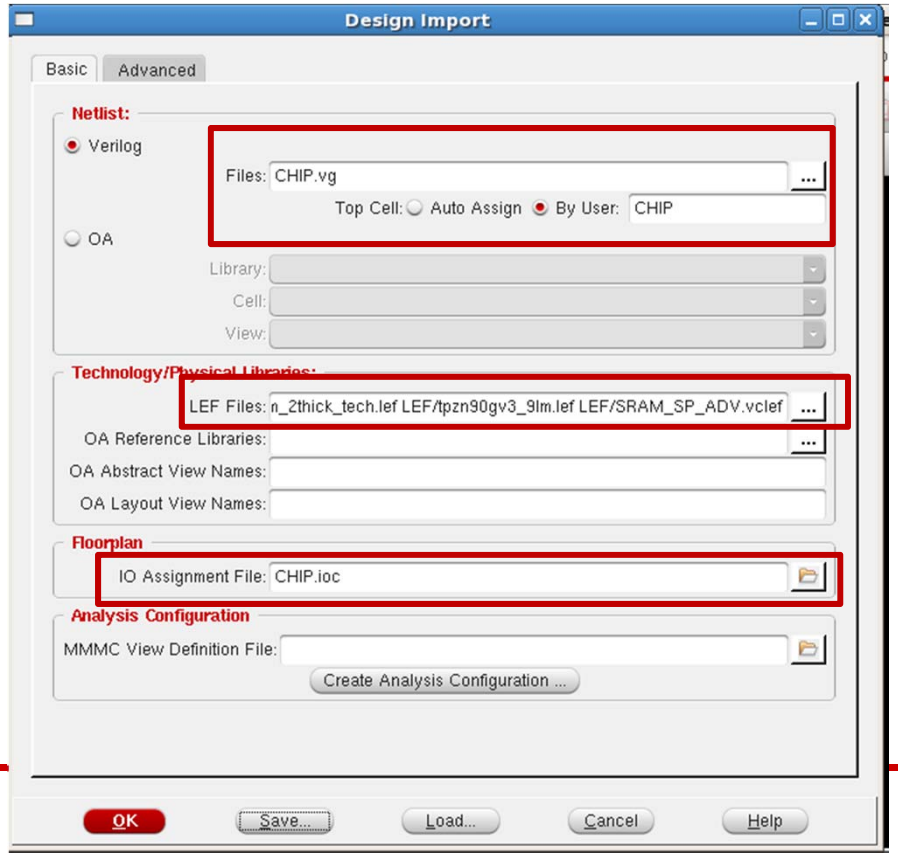
  For example: cd bisr/encounter/SOC/
- *unix %> encounter*

(Do not run in the background mode !!)



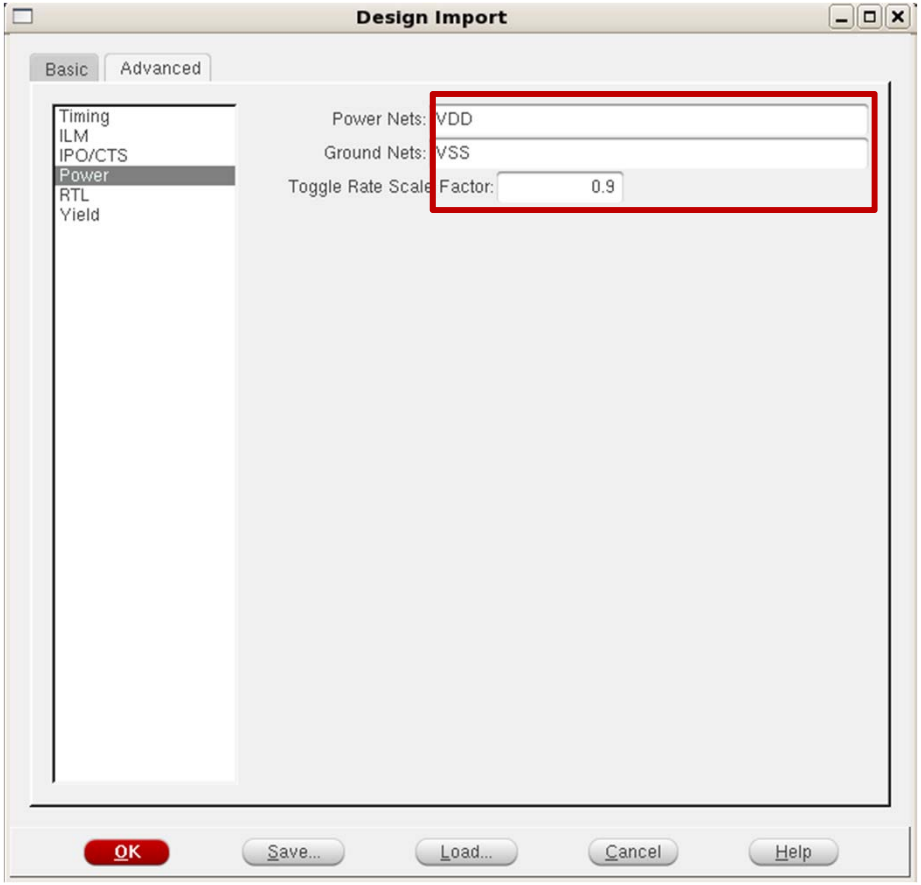
Import Design <Design>

- ***Design/Design Import***
- Verilog Files: your gate-level netlist
- Tot Cell
- LEF Files (*.lef): including all the LEF files of cell libraries & hard blocks
- IO Assignment File: *.ioc



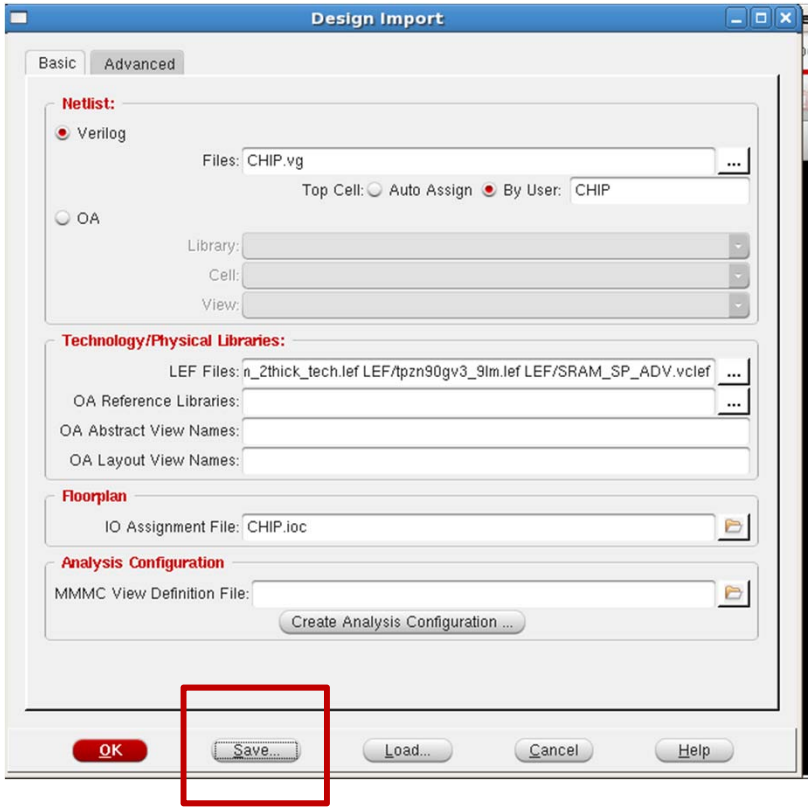
Import Design <Power>

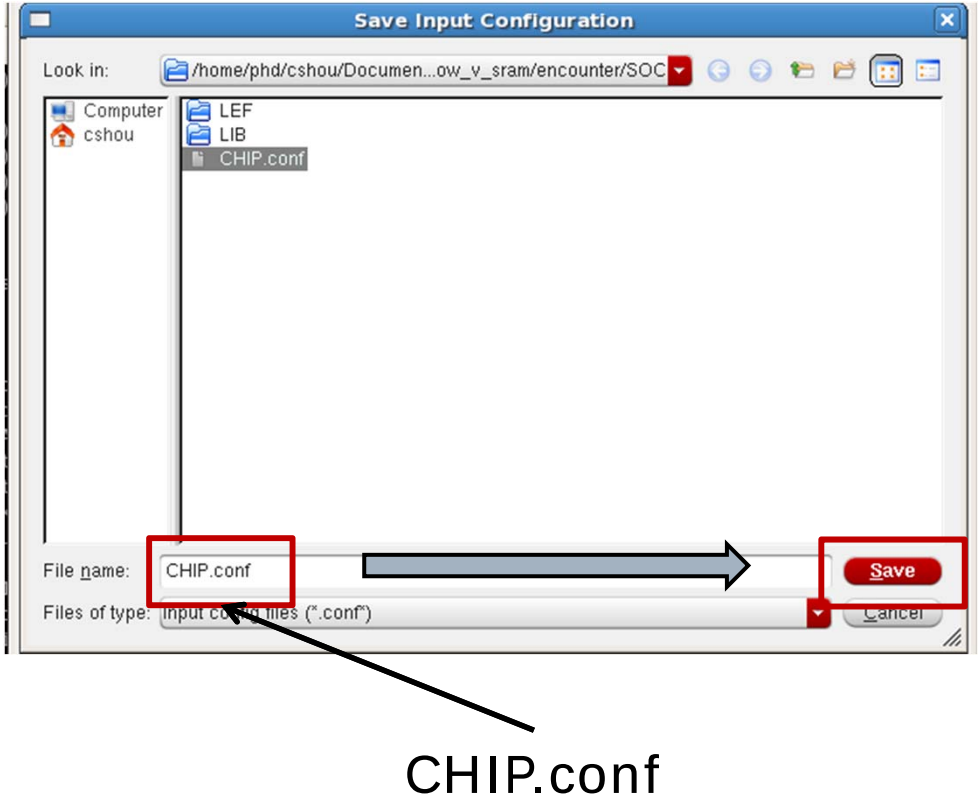
- Power Nets: VDD
- Ground Nets: VSS
- Toggle Rate Scale Factor: 0.9



Import Design <Save Conf.>

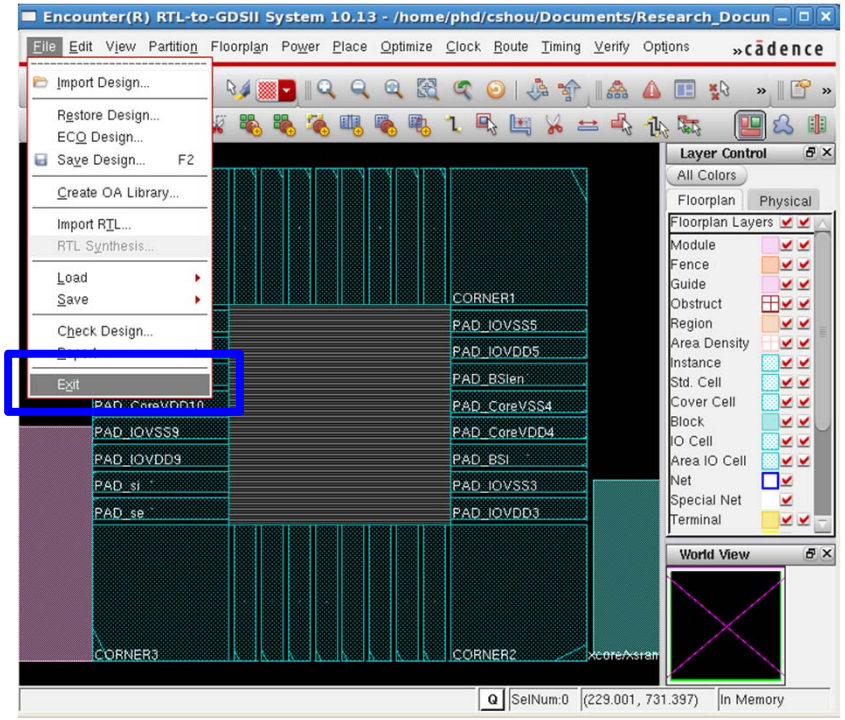
- Before OK~
- Save your import design to a configuration file



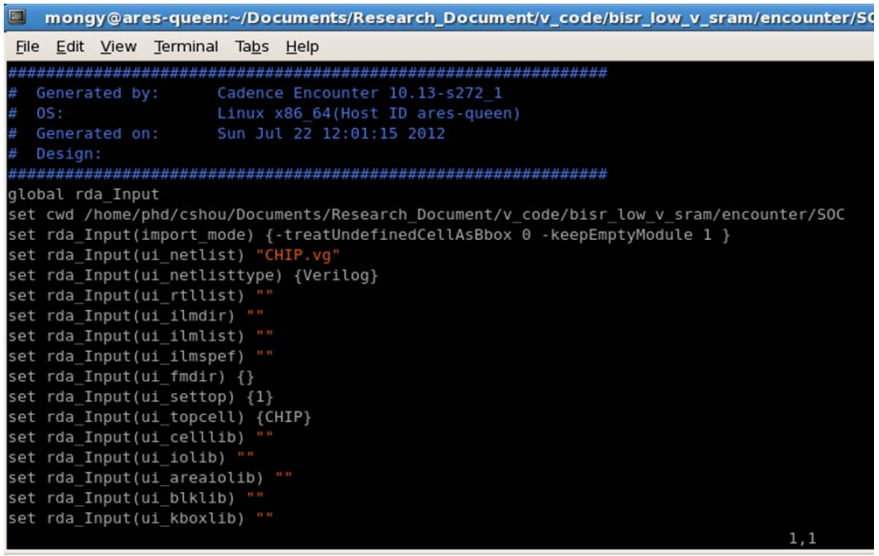


Close Encounter

- Due to some files can not input from GUI, therefore, we need to setup the files by write commands to configuration file (CHIP.conf)



Linux> vi CHIP.conf



Import Design <Design> (cont.)

=*

Due to No GUI, it requires to write the commands to .conf

- LIB Files (*.lib):
  - Max Timing Libraries
  - Min Timing Libraries
  - Common Model Libraries

Find a line denoted with

set rda_Input(ui_timelib,max) “” ⇐ max timing libraries

set rda_Input(ui_timelib,min) “” ⇐ min timing libraries

set rda_Input(ui_timelib) “” ⇐ typical timing libraries

Import Design <Timing>

=*

Due to No GUI, it requires to write the commands to .conf

- Capacitance Table File
- Timing Constraint File: *.sdc
- QX Tech File: FireIce capacitance file
- QX Library Directory:

Find a line denoted with

set rda_Input(ui_captbl_file) “” ⇐ capacitor libraries

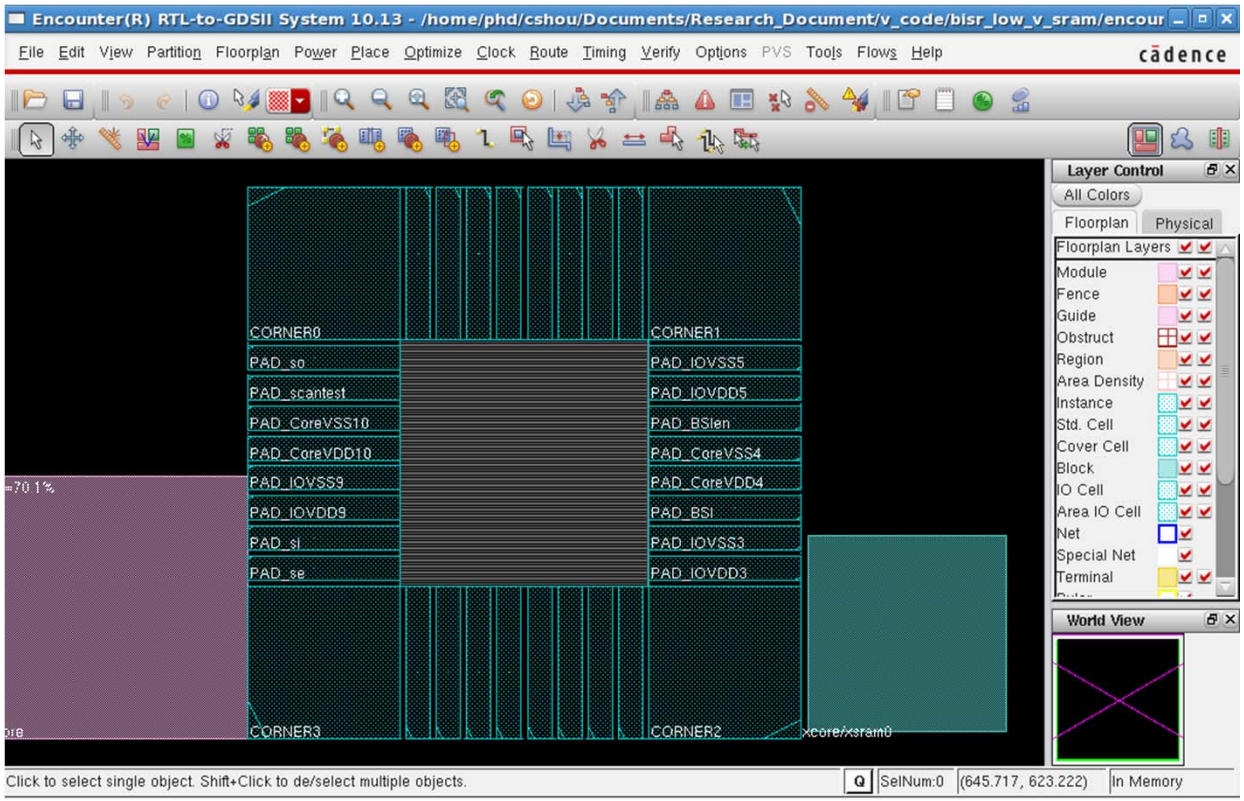
set rda_Input(ui_timingcon_file) “” ⇐ timing constraint file

set rda_Input(ui_qxtech_file) “” ⇐fireice capacitance file

set rda_Input(ui_qxlib_file) “” ⇐ fireice capacitance folder

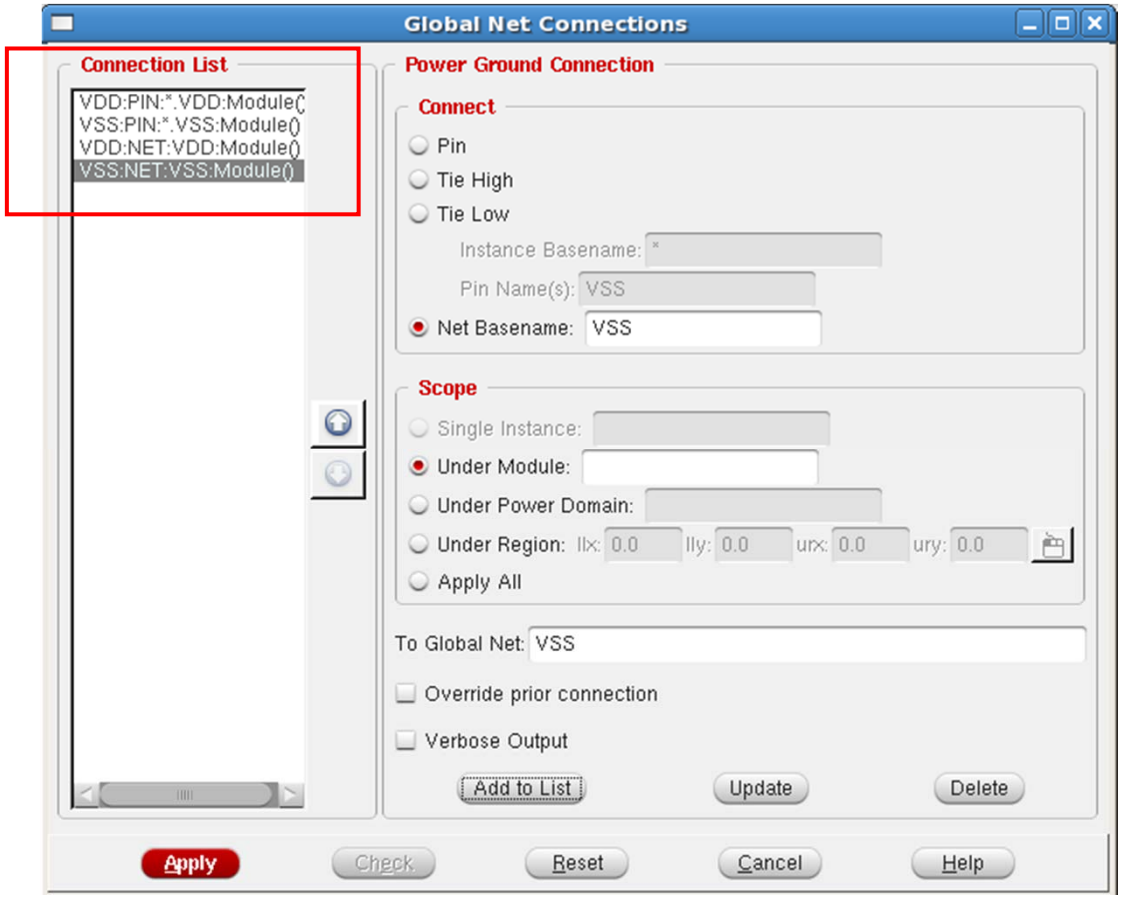
After Initialization

- Based on configuration file, the soc encounter shows the blocks



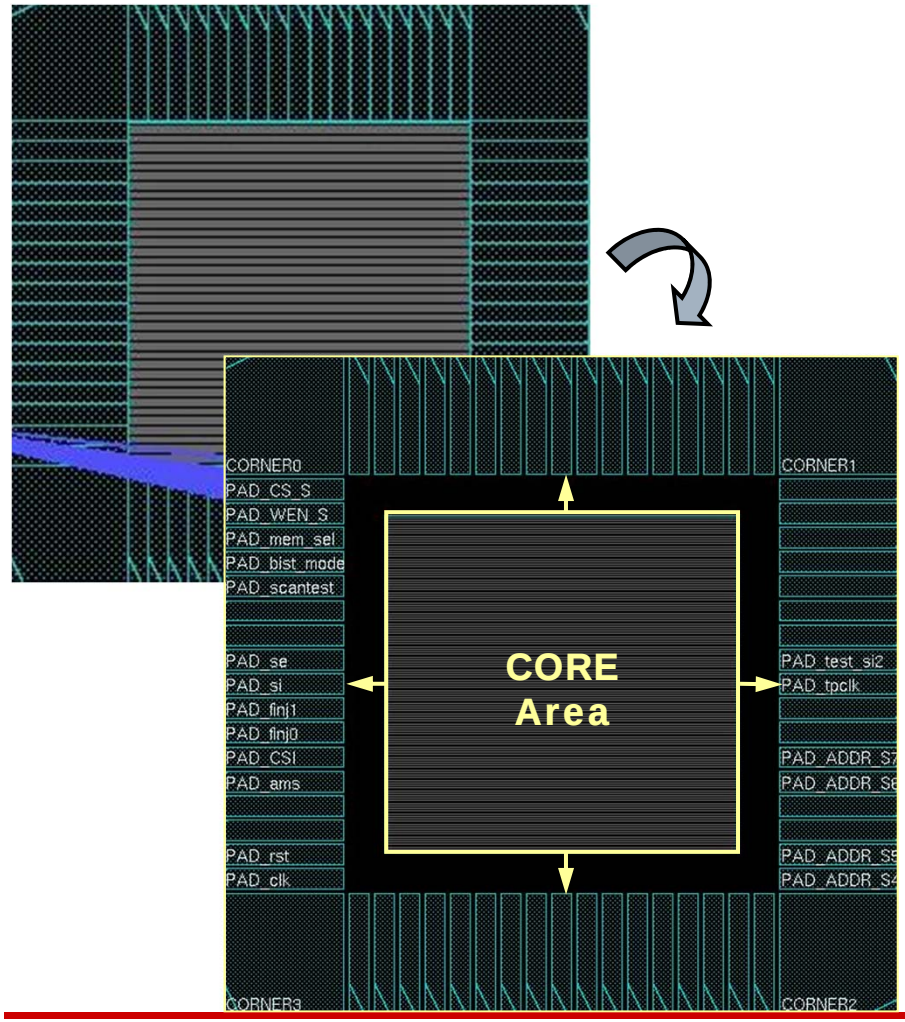
Global Net Connection

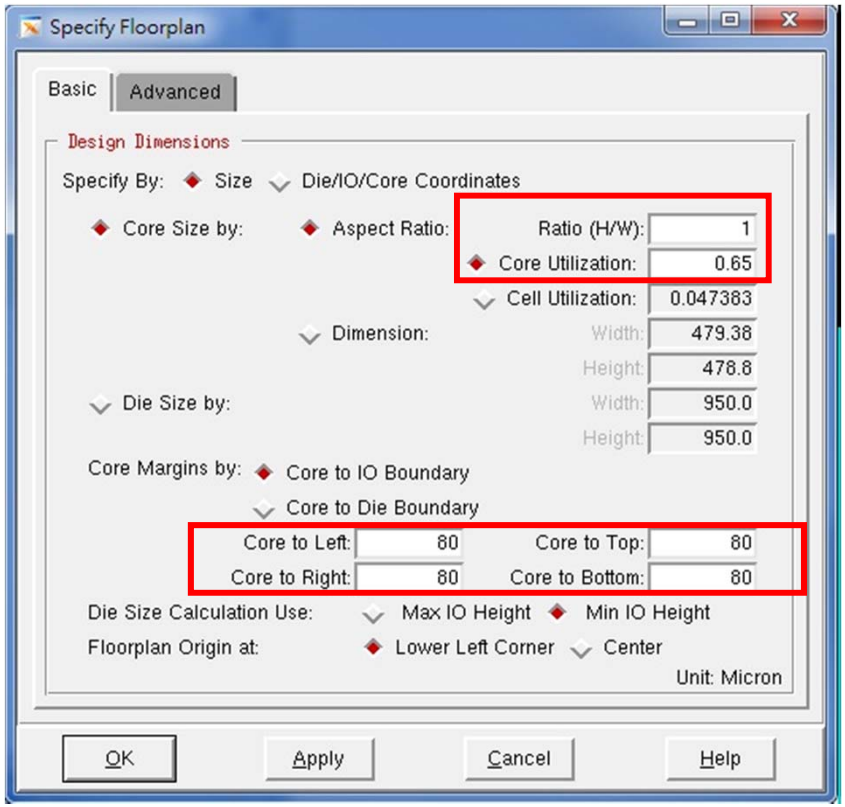
- ***Floorplan/Global Net Connections***



Specify Floorplan

Floorplan/Specify Floorplan





Specify Scan Chain

- *encounter %> specifyScanChain ScanChainName*
  - start {ftname | instPinName}
  - start {ftname | instPinName}
- *encounter %> scantrace*

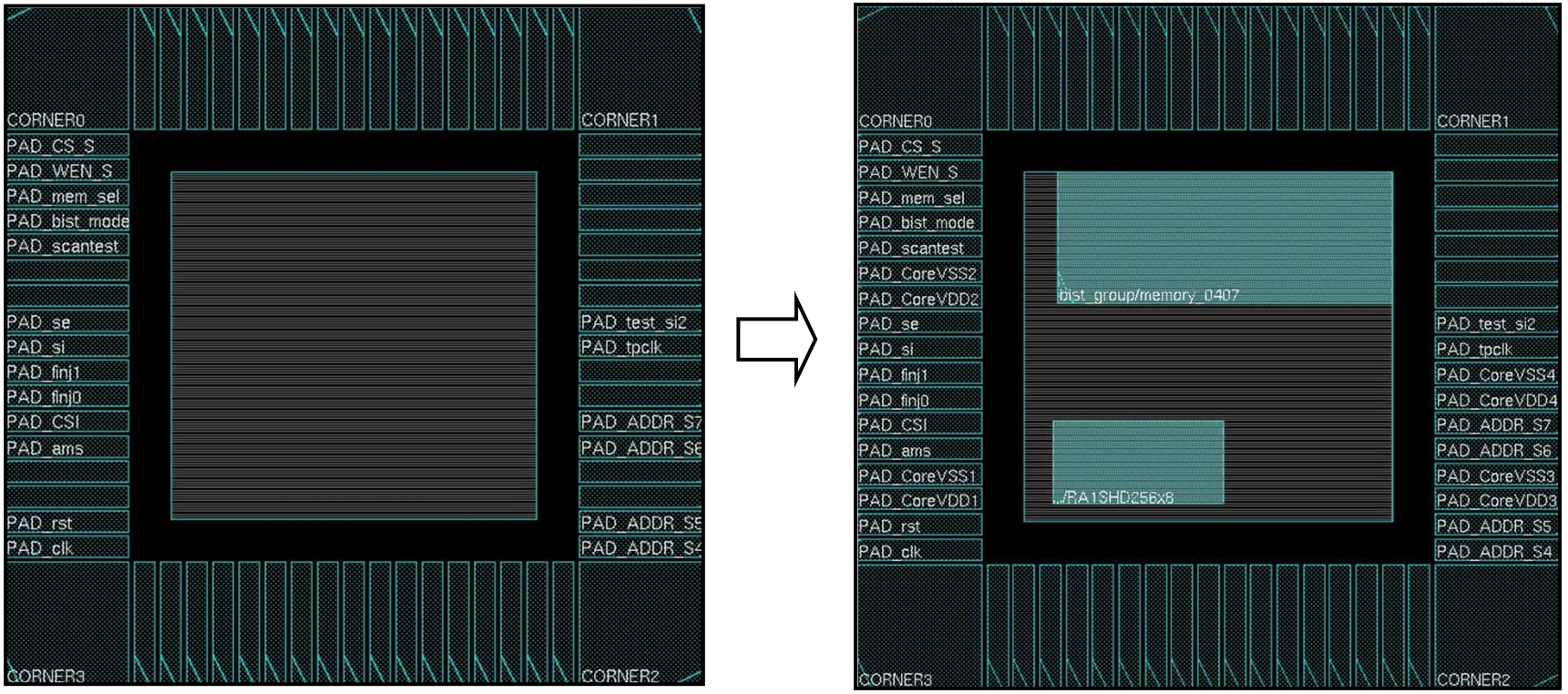
Ex:

```
encounter 2> specifyScanChain scan1 -start PAD_si/C -stop PAD_so/I
encounter 3> specifyScanChain scan2 -start PAD_test_si2/C -stop PAD_test_so2/I
encounter 4> scantrace
Tracing scan chain: scan1
Successfully traced scan group scan1 (99 elements: 97 scan bits).
Tracing scan chain: scan2
Successfully traced scan group scan2 (57 elements: 56 scan bits).
*** Scan Trace Summary:
Successfully traced scan group scan1 (99 elements: 97 scan bits).
Successfully traced scan group scan2 (57 elements: 56 scan bits).
Successfully traced 2 scan groups (total 156 elements: 153 scan bits).
INFO: Performed sanity check on scan group scan1 (+1 scan edge  marked as fixed).
INFO: Passed sanity check on scan group scan2.
*** Scan Sanity Check Summary:
*** 1 scan group  passed sanity check.
*** 1 scan group  corrected sanity check (total +1 fixed scan edge ).
```

(result)

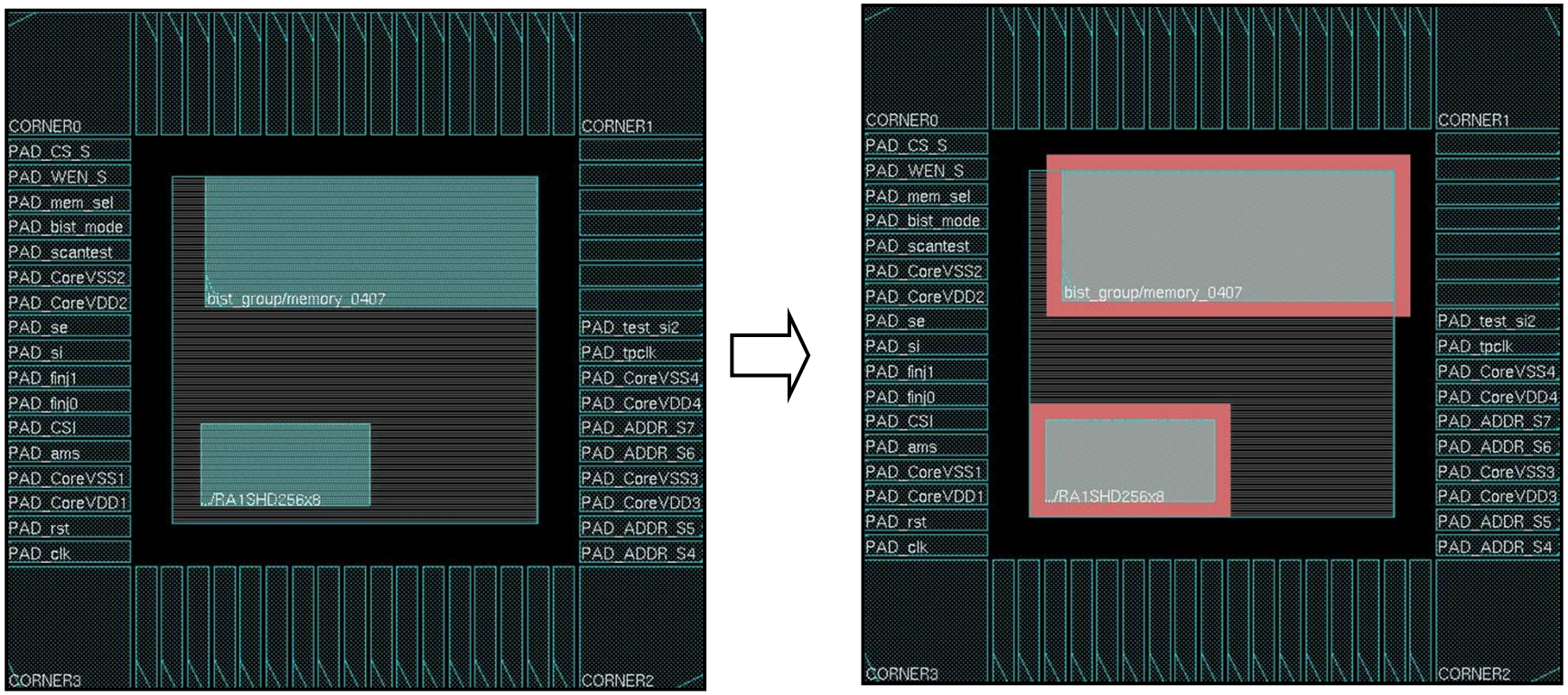
Hard Block Placement

- Move/Resize/Reshape floorplan object



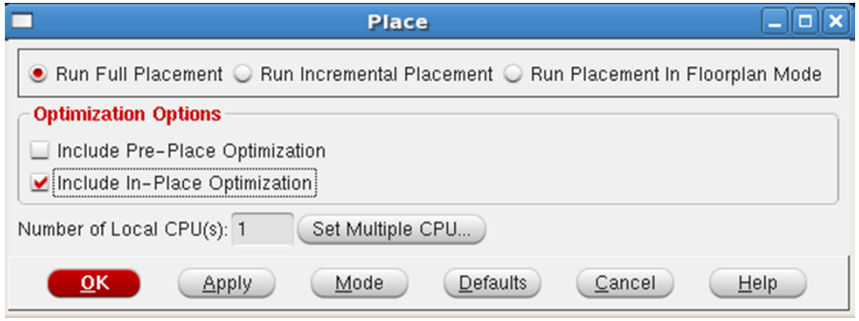
Edit Block Halo

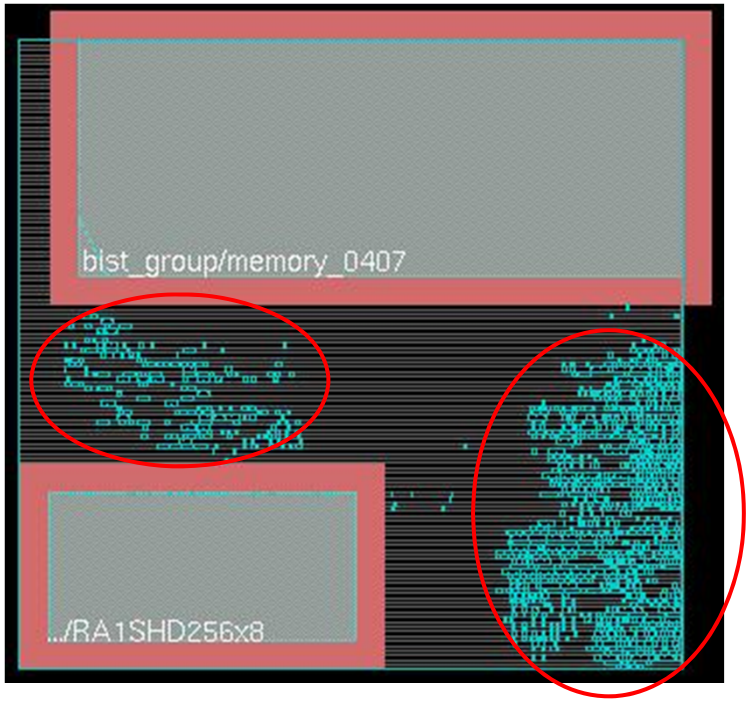
- ***Floorplan/Edit Block Halo***
- Reserve space without standard cell placement



Standard Cell Placement

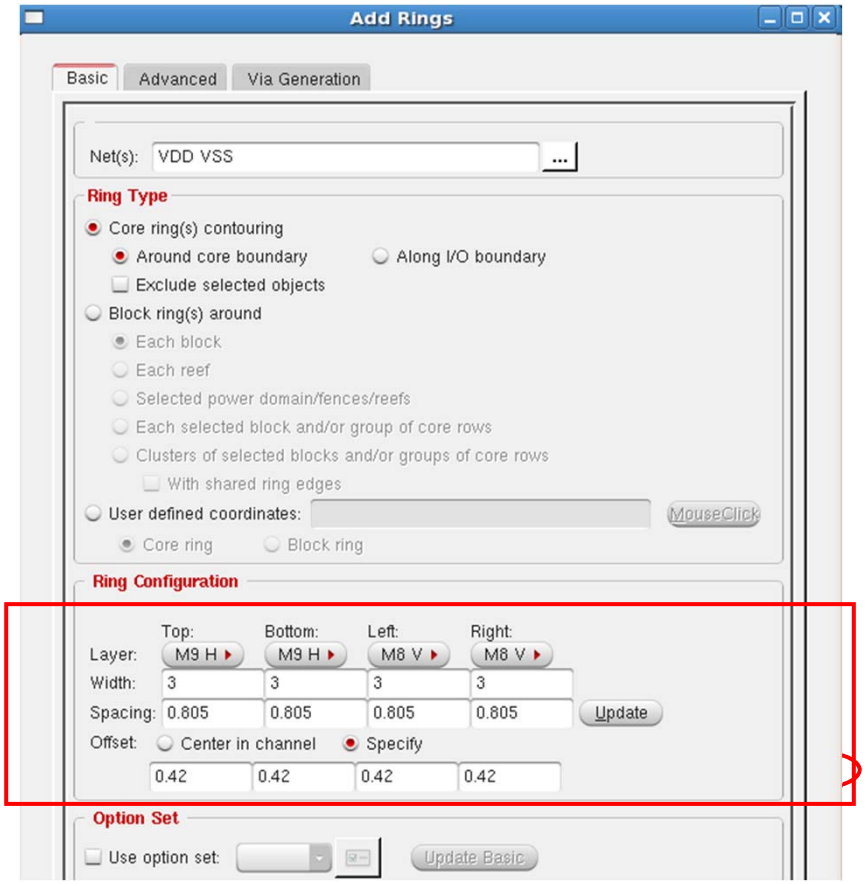
- ***Place/Place***

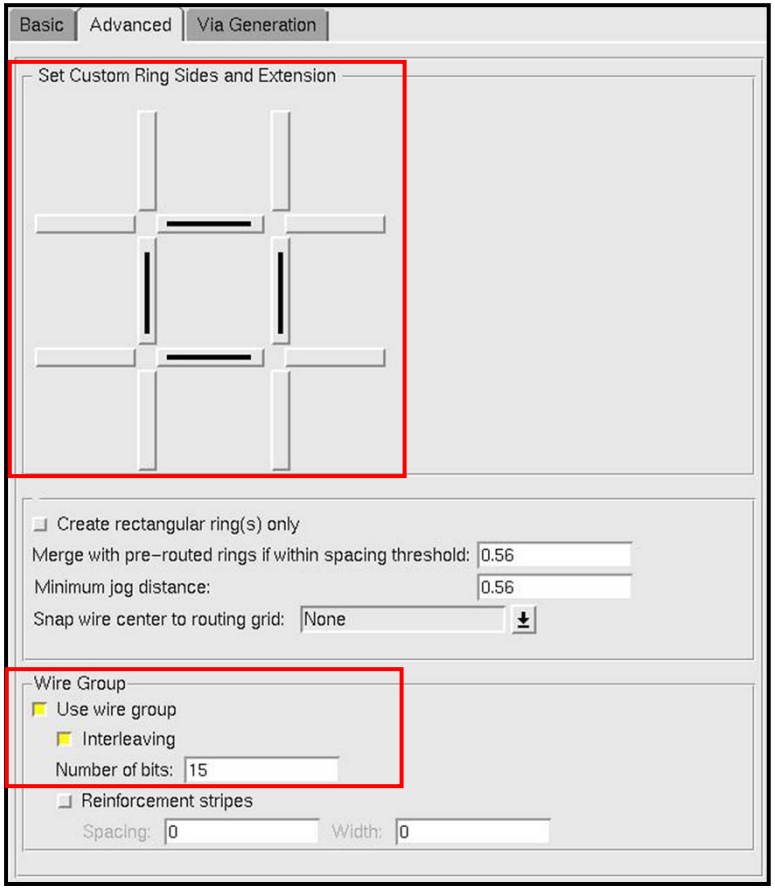




Power Planning – Add Rings

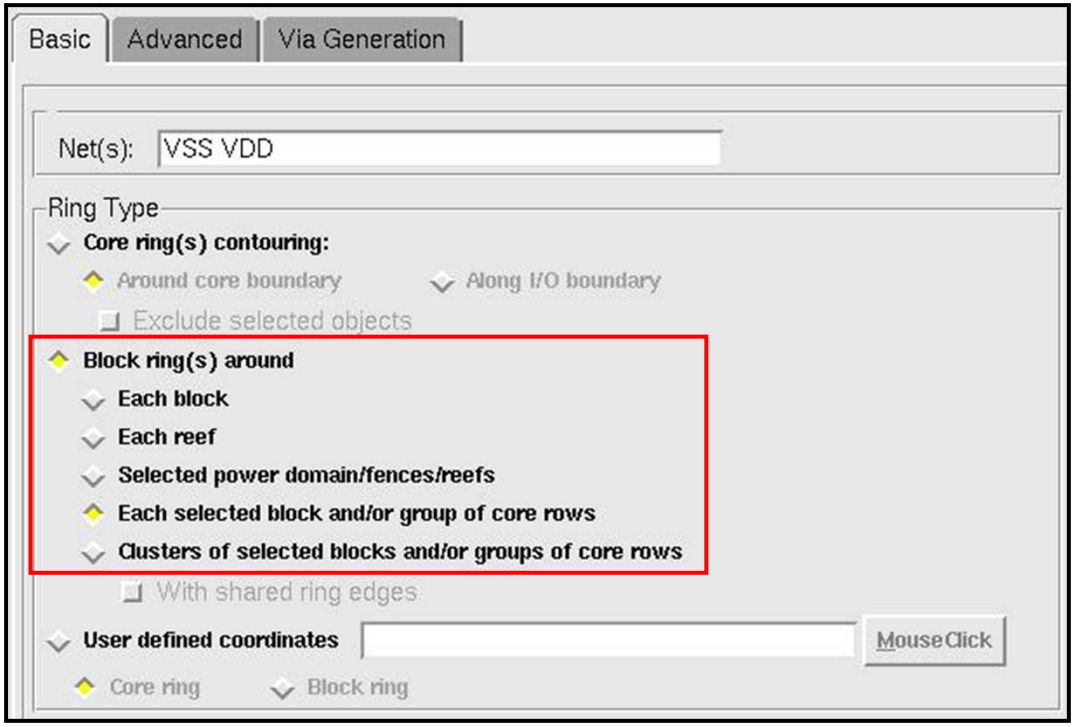
- ***Floorplan/Custom Power Planning/Add Rings***

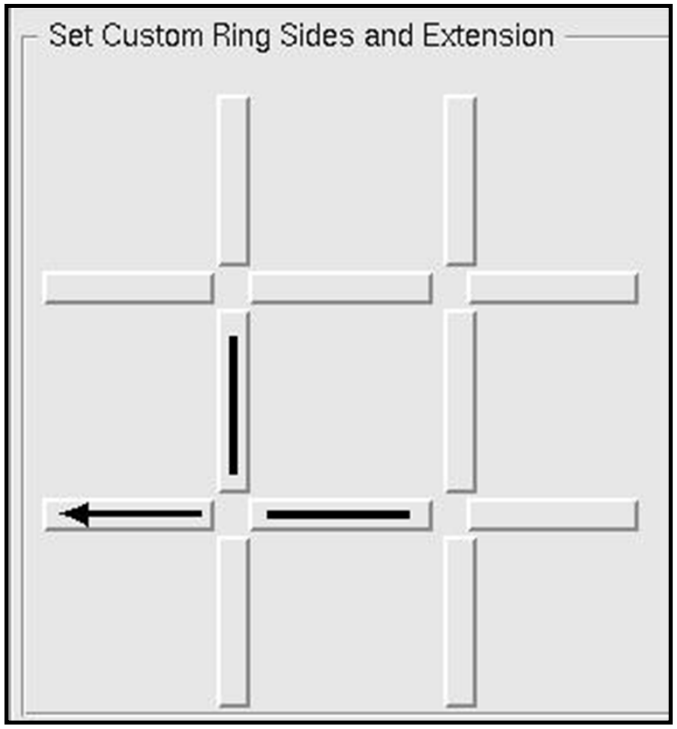




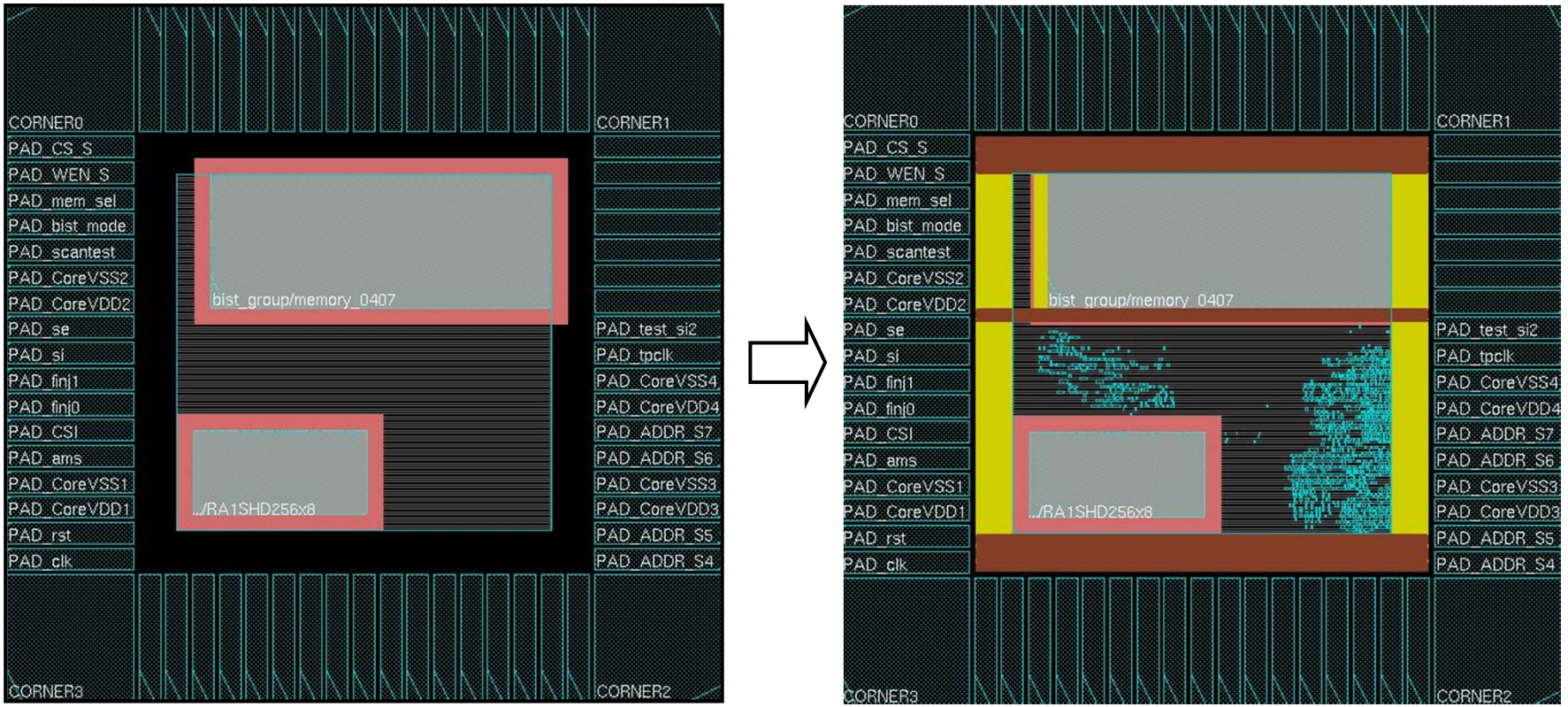
Power Planning – Add Block Rings

- ***Floorplan/Custom Power Planning/Add Rings***





Example for Power Rings

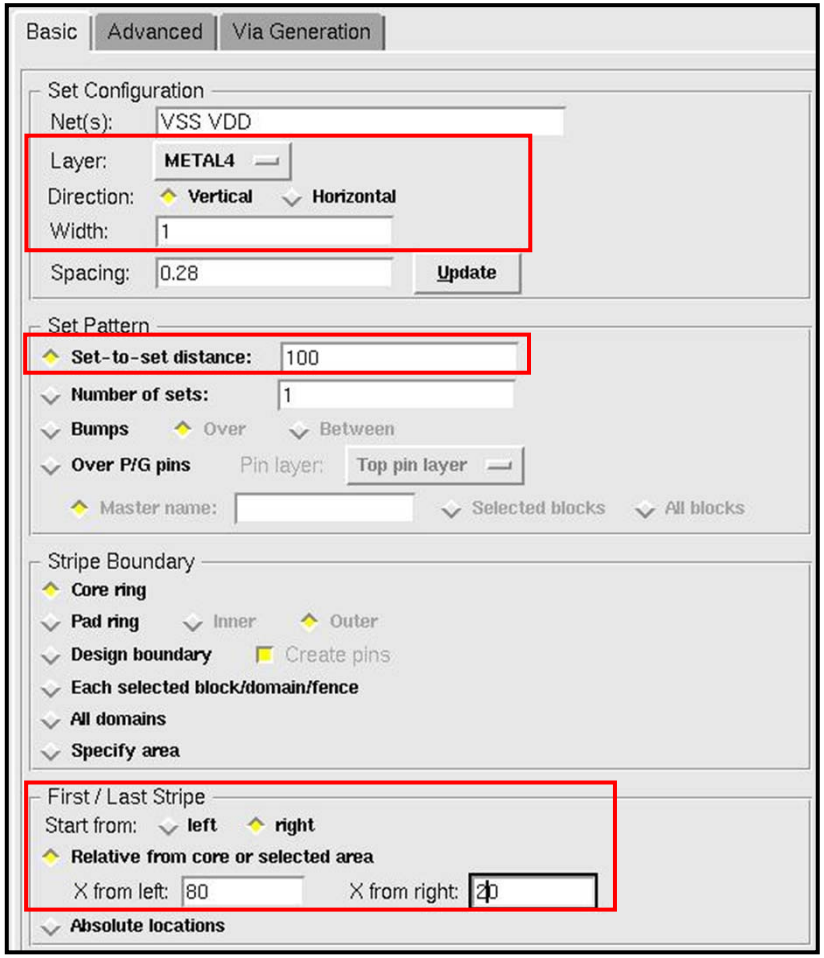


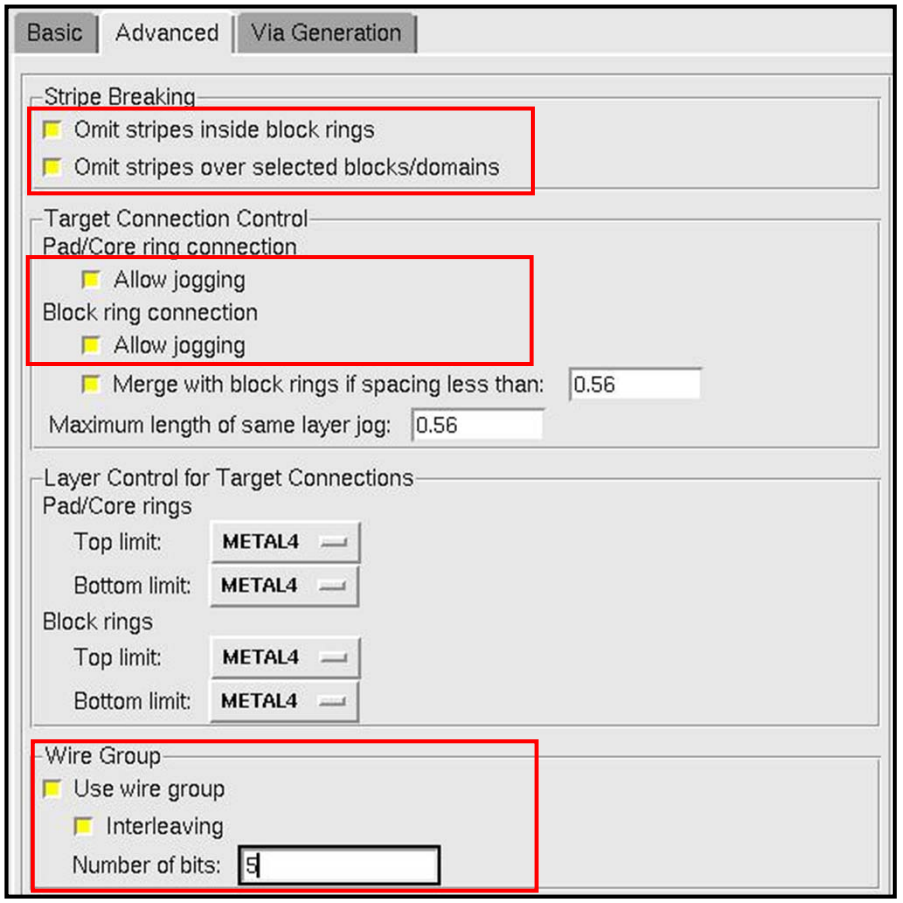
PAD Pins

- ***Route/SRoute***

Power Planning – Add Stripes

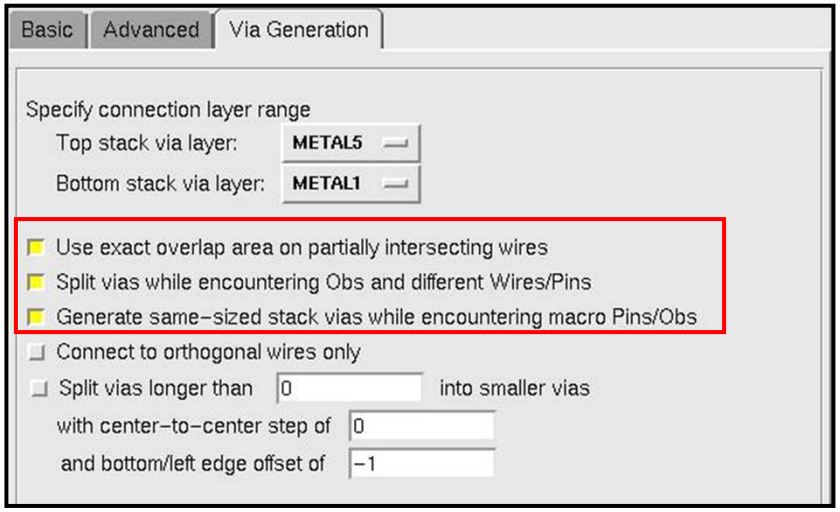
- ***Floorplan/Custom Power Planning/Add Stripes***

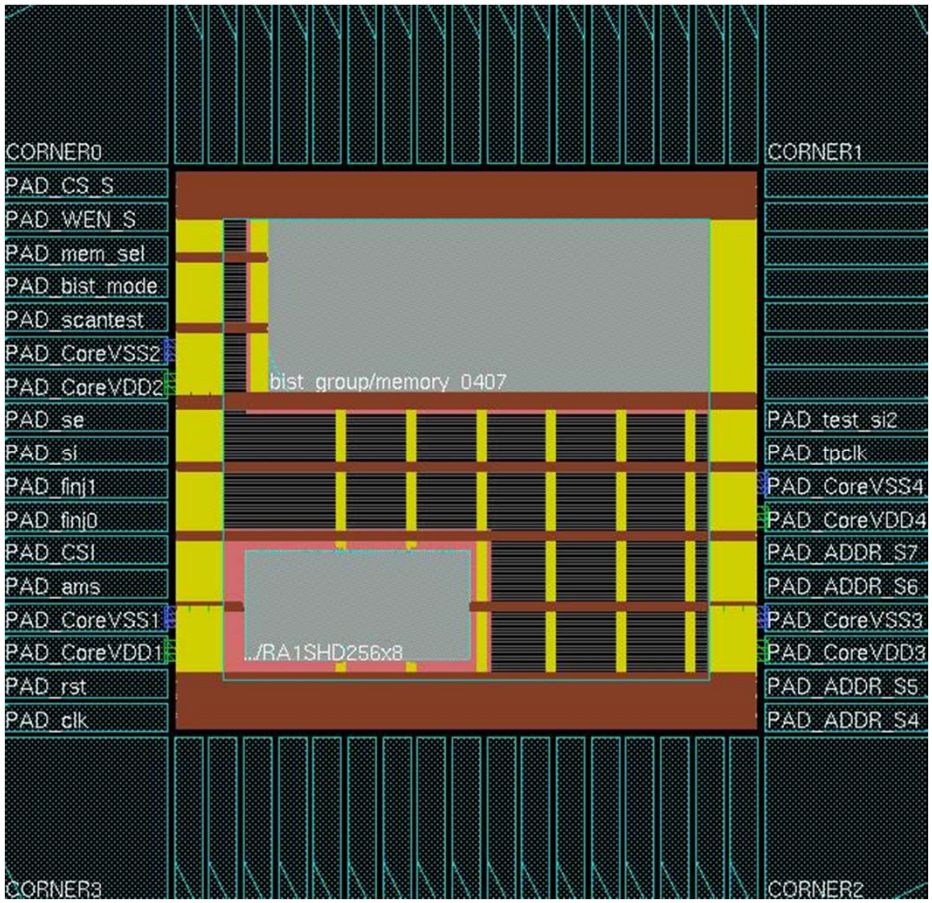




Power Planning – Add Stripes (Cont')

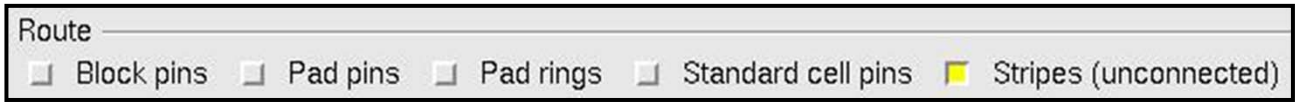
Ex:

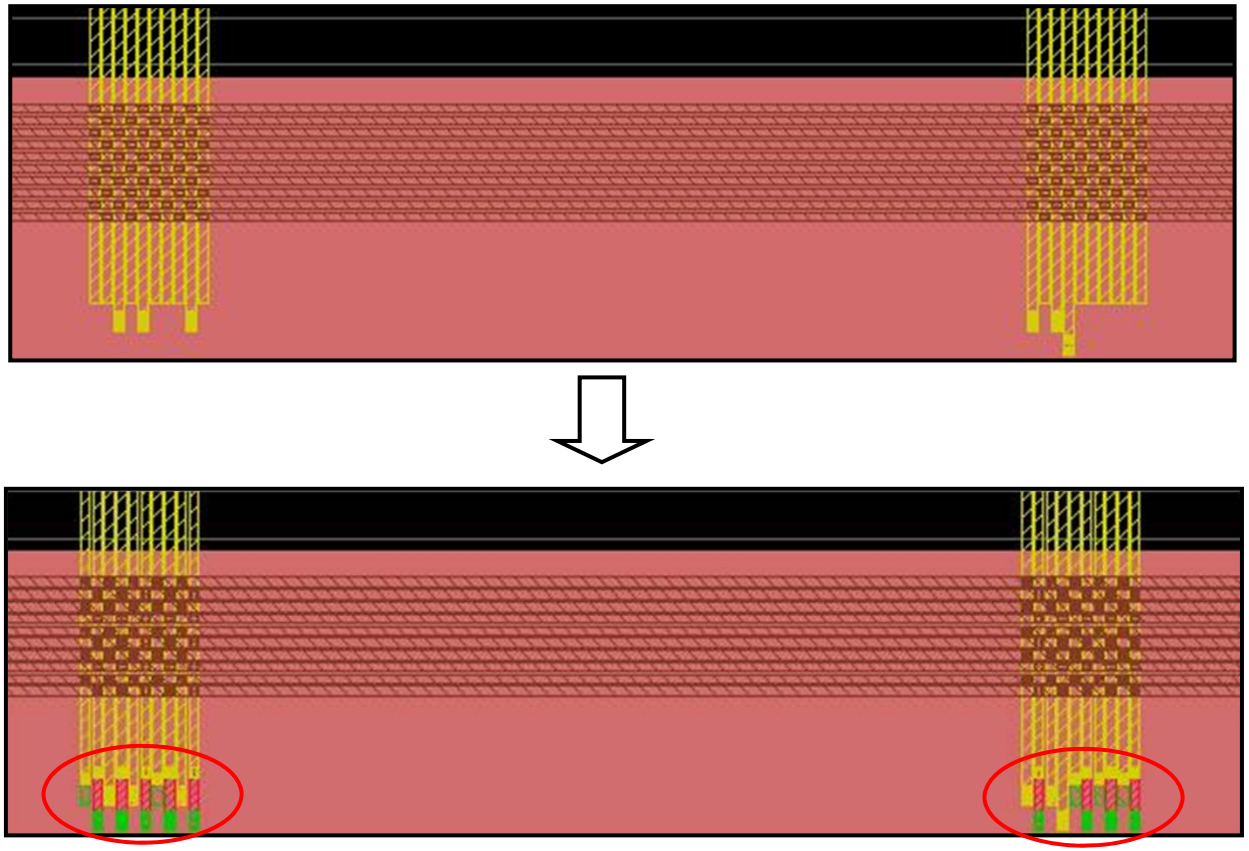




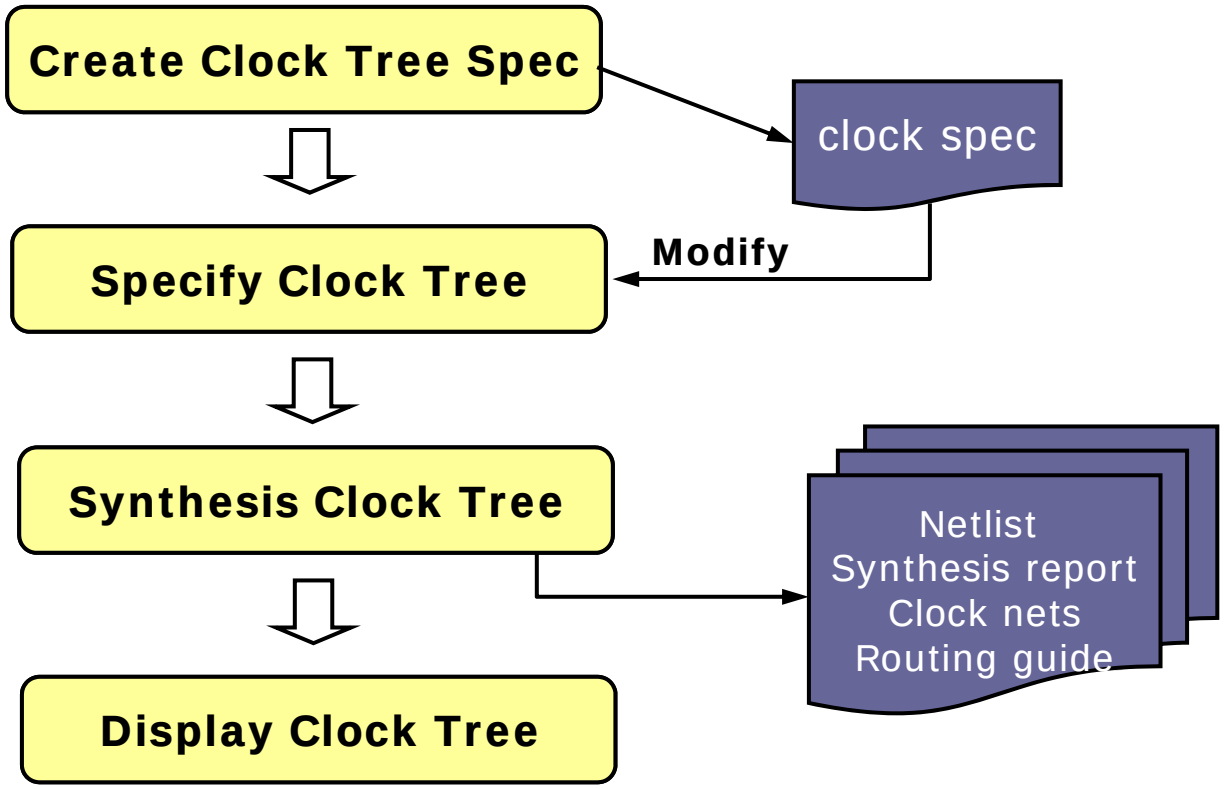
Fix Un-Connected Stripes

- ***Route/SRoute***



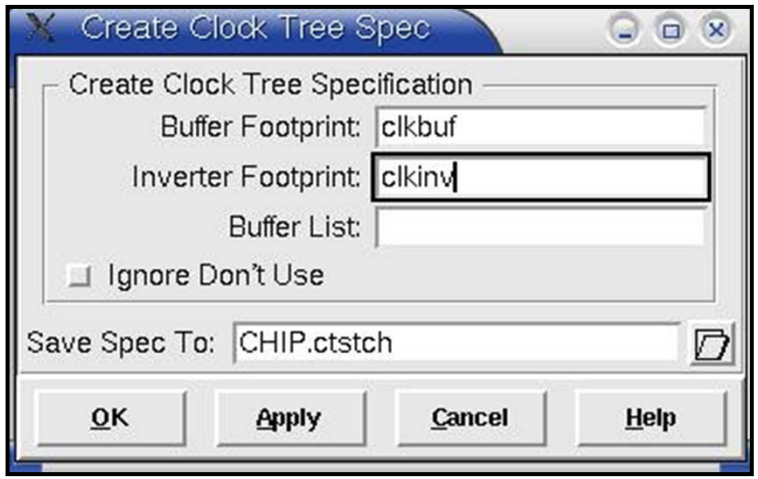


Flow Clock Tree Synthesize



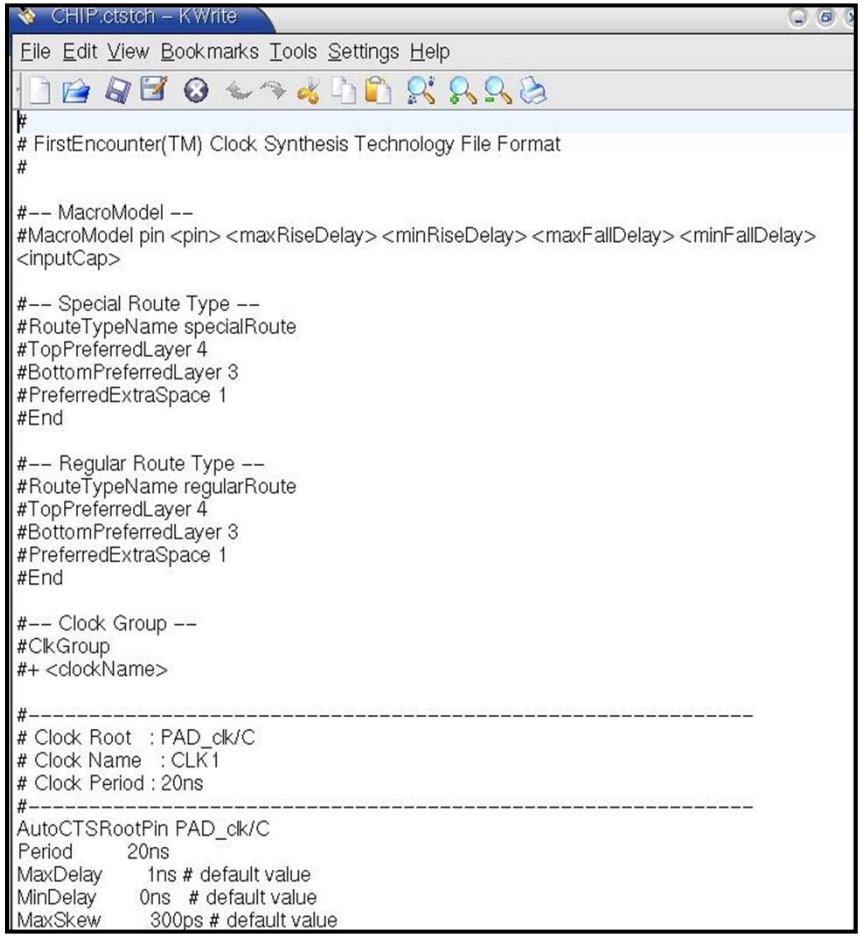
Create / Specify / Synthesis Clock Tree Spec.

- ***Clock/Create Clock Tree Spec***



- ***Clock/Specify Clock Tree***

- ***Clock/Synthesis Clock Tree***



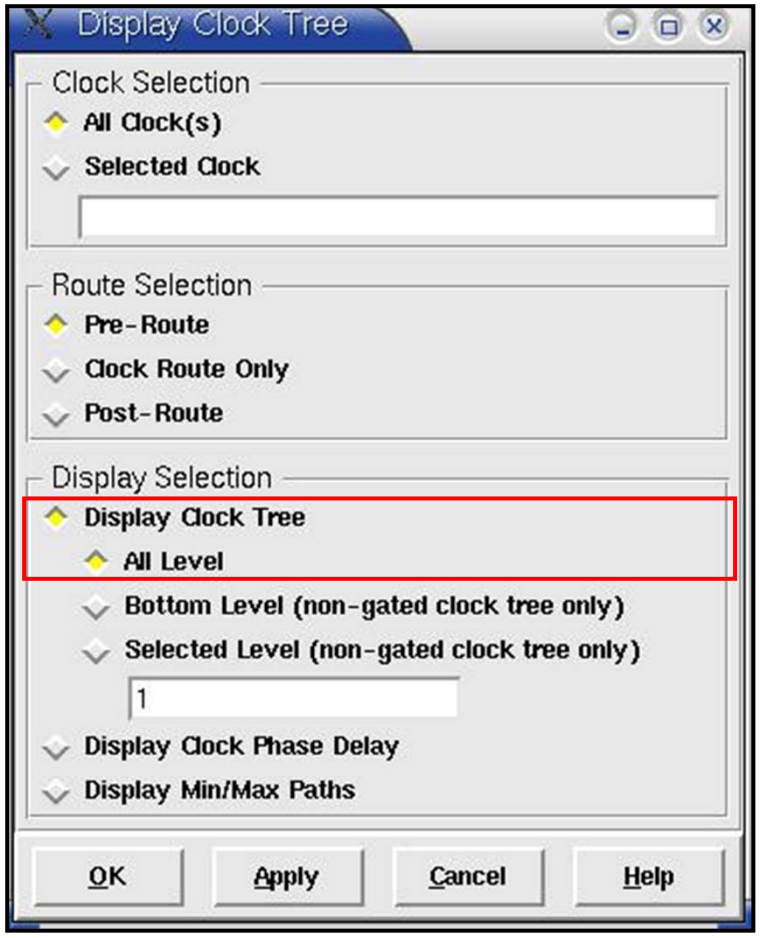
(Clock Spec.)

Example for CTS Report

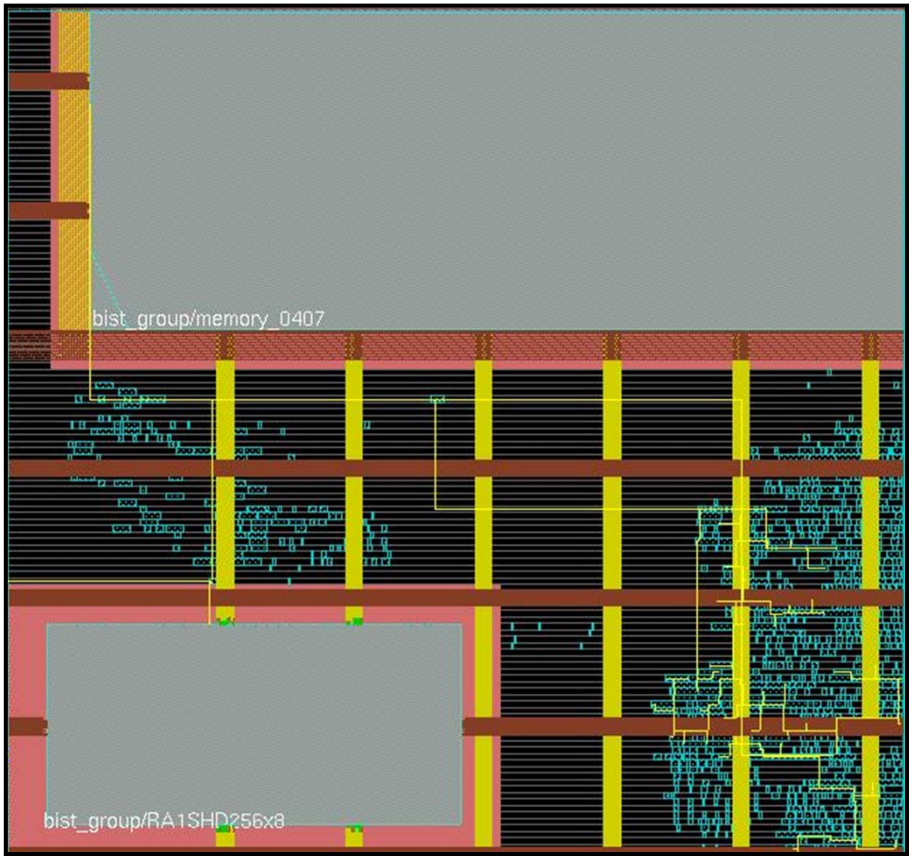
```
Nr. of Subtrees              : 1
Nr. of Sinks                 : 99
Nr. of Buffer                : 5
Nr. of Level (including gates) : 1
Max trig. edge delay at sink(F): bist_group/bist/m0/shift_reg_reg_10_/CKN 230.9(ps)
Min trig. edge delay at sink(R): bist_group/memory_0407/clock 176.8(ps)


                          (Actual)            (Required)
Rise Phase Delay             : 176.8~217.5(ps)       0~1000(ps)
Fall Phase Delay             : 189.2~230.9(ps)       0~1000(ps)
Trig. Edge Skew              : 54.1(ps)              300(ps)
Rise Skew                    : 40.7(ps)
Fall Skew                    : 41.7(ps)
Max. Rise Buffer Tran        : 58.4(ps)              400(ps)
Max. Fall Buffer Tran        : 58.4(ps)              400(ps)
Max. Rise Sink Tran          : 177.9(ps)             400(ps)
Max. Fall Sink Tran          : 165.4(ps)             400(ps)
Min. Rise Buffer Tran        : 23.2(ps)              0(ps)
Min. Fall Buffer Tran        : 23.2(ps)              0(ps)
Min. Rise Sink Tran          : 97.9(ps)              0(ps)
Min. Fall Sink Tran          : 92.4(ps)              0(ps)



***** NO Max Transition Time Violation *****

***** NO Min Transition Time Violation *****

***** NO Max_Fanout Violation *****
```

Display Clock Tree

- ***Clock/Display/Display Clock Tree***

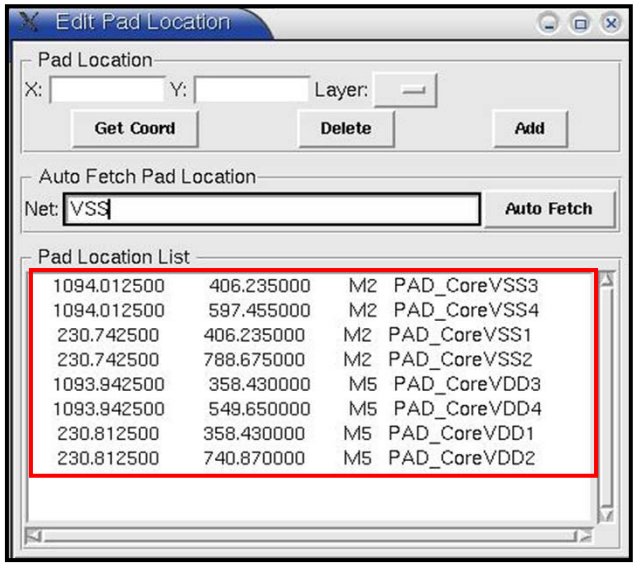


Ex:

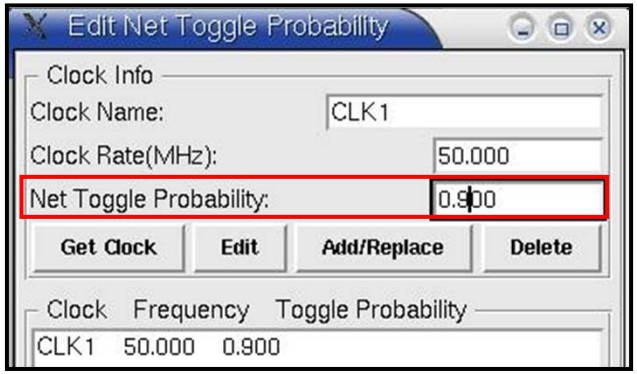


Power Analysis

Power/Edit Pad Location



Power/Edit Net Toggle Probability



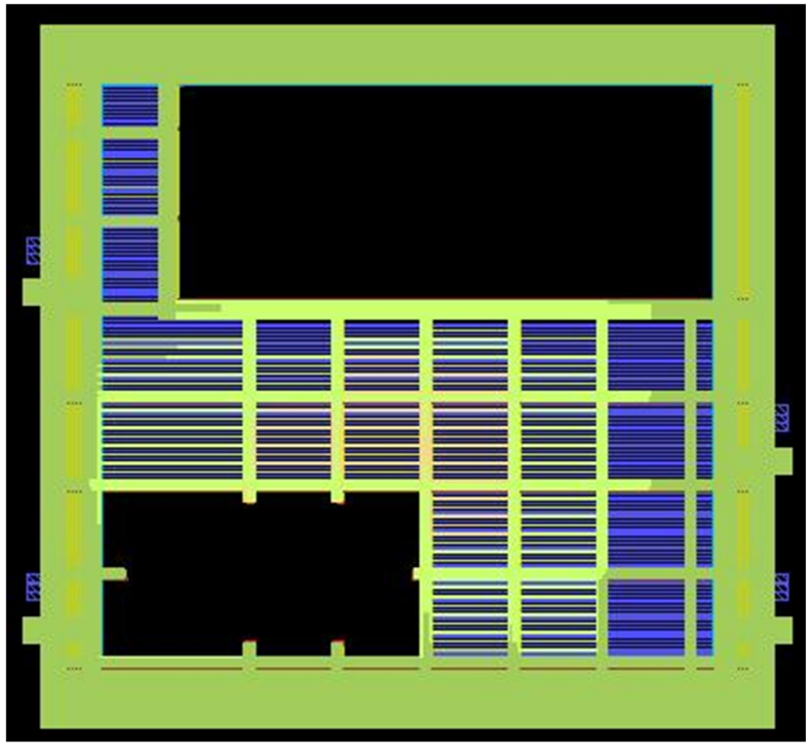
Power/Power Analysis/Statistical

Ex:

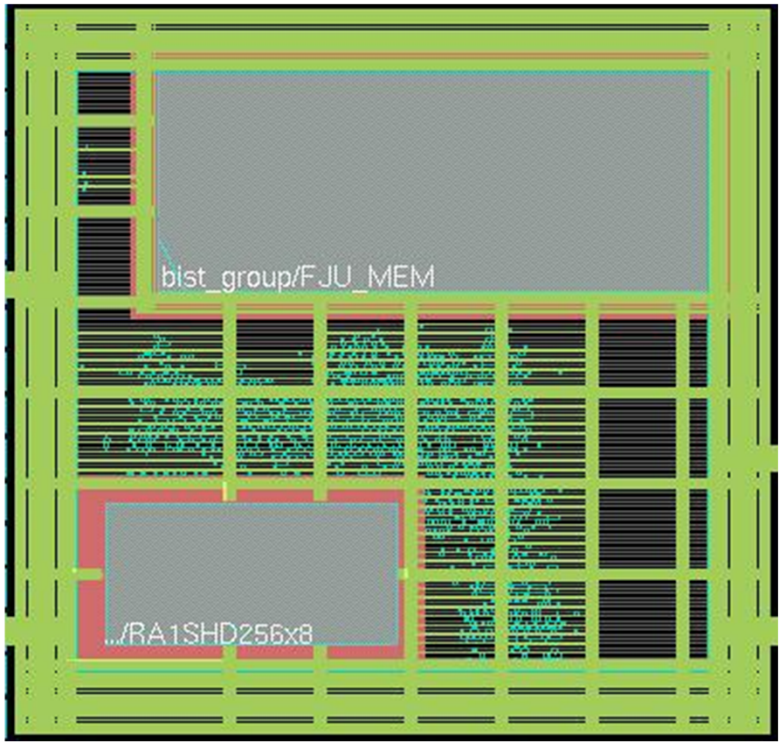
```
##########################################
# The Power Analysis Report for VDD net      #
##########################################
power supply: 1.98 v
average power(default): 1.0470e+01 mw
    average switching power(default): 2.3212e+00 mw
    average internal power(default): 8.1442e+00 mw
    average leakage power(default): 4.7600e-03 mw
    average user specified power(default): 0.0000e+00 mw
average power by clock domain category:
    clock domain(CLK1, 0.9) : 1.0282e+01 mw
       clock tree power : 4.1149e+00 mw
       non clock tree power : 6.1672e+00 mw
    unclock domain(0,2) : 1.8807e-01 mw
average power by cell category:
    core:  7.3701e+00 mw
    block: 3.1001e+00 mw
    io:    0.0000e+00 mw
average power(considered in rail analysis): 1.0470e+01 mw
worst IR drop average analysis: 1.9718e-03 v
  number of nodes in rail network: 16645 nodes
worst EM:
    "M1"  5.2000e-02 mA/u
    "M2"  0.0000e+00 mA/u
    "M3"  3.9142e-01 mA/u
    "M4"  3.9142e-01 mA/u
    "M5"  2.2647e-01 mA/u
    "V12" 1.4821e-02 mA/cut
    "V23" 1.4821e-02 mA/cut
    "V34" 9.7855e-02 mA/cut
    "V45" 2.8280e-02 mA/cut
biggest toggled net: clk__L1_N0
    no. of terminal: 93
    total cap: 7.6044e+02 ff
```

(Power Analysis Report)

Example for Rail Analysis of IR-Drop & EM



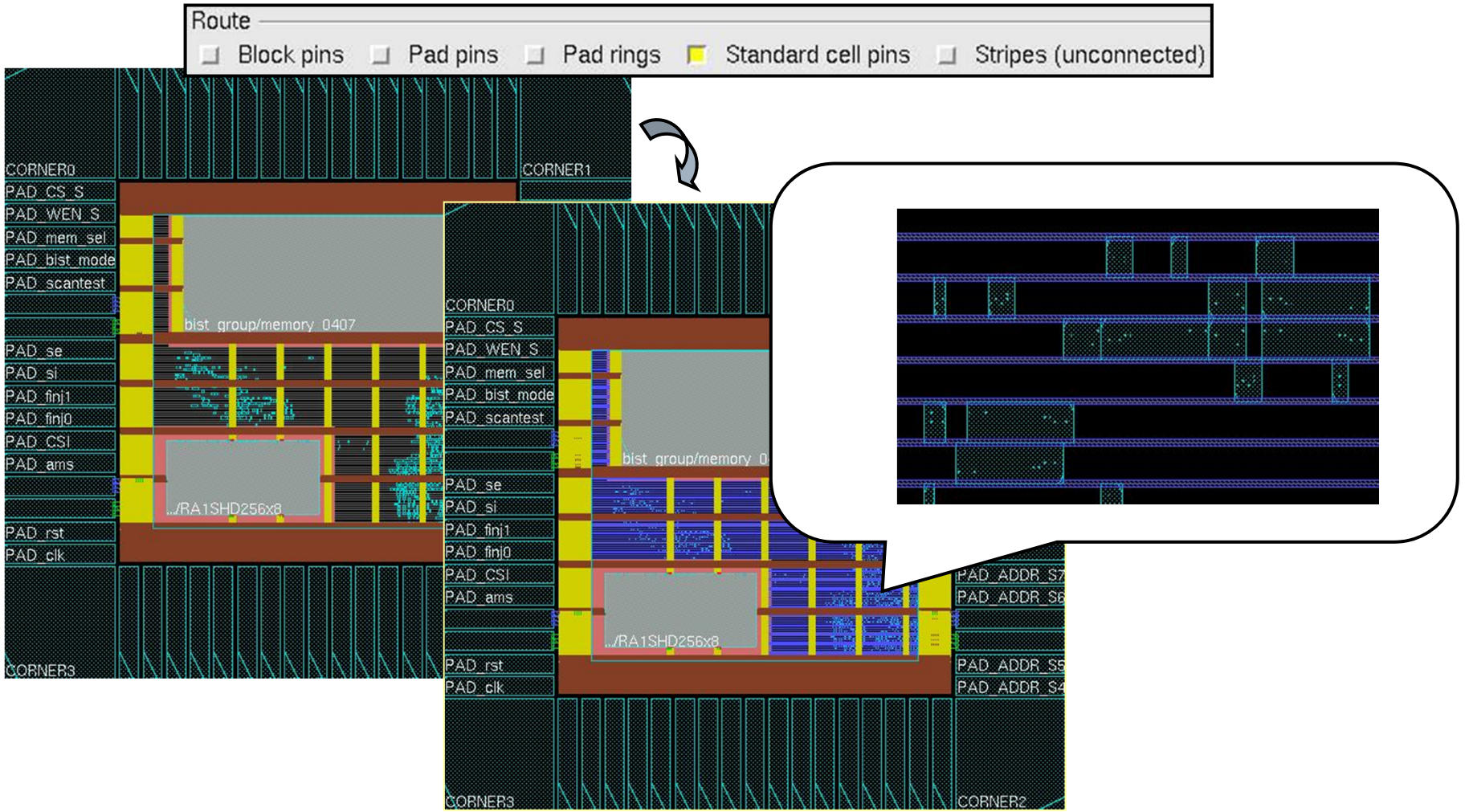
(IR-Drop)



(EM)

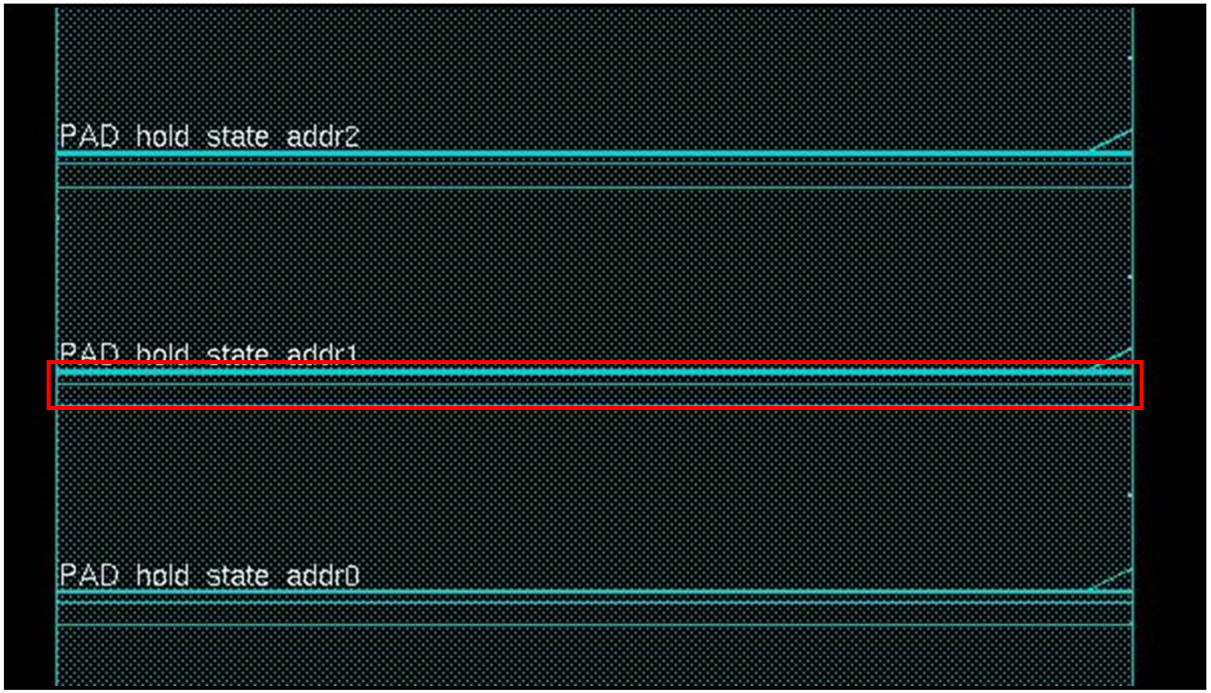
Power Route

- ***Route/SRoute***



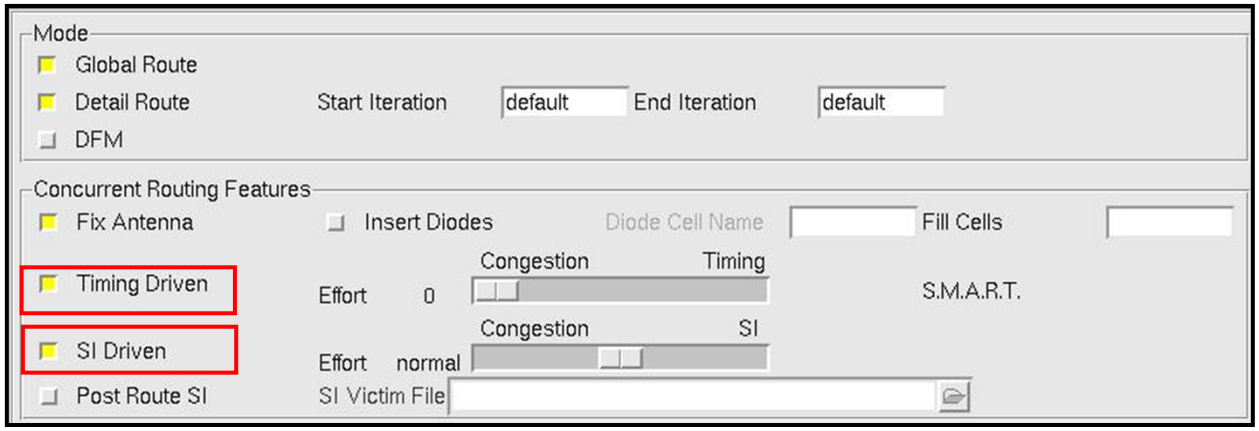
IO Filler

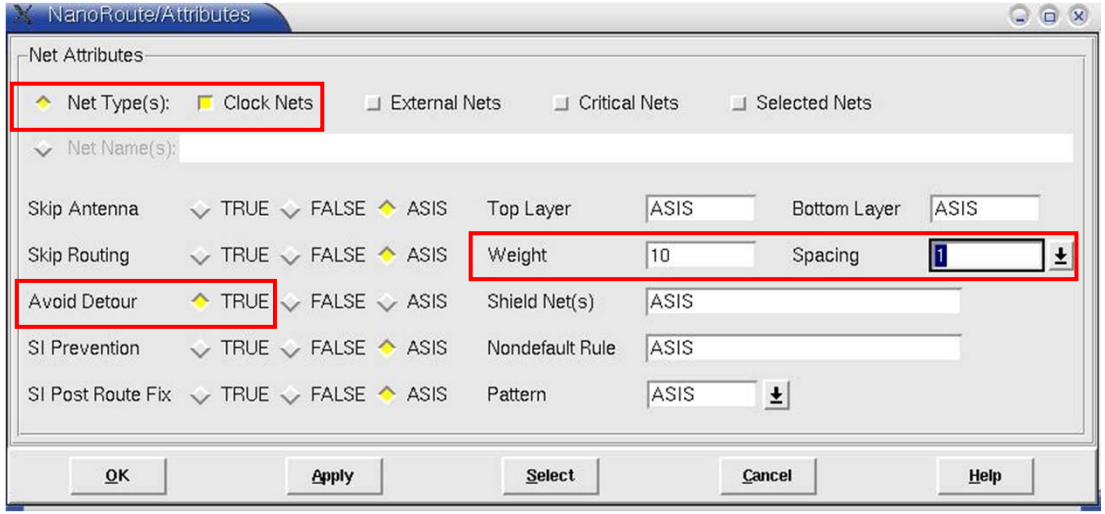
- *encounter %> source addIoFiller.cmd*



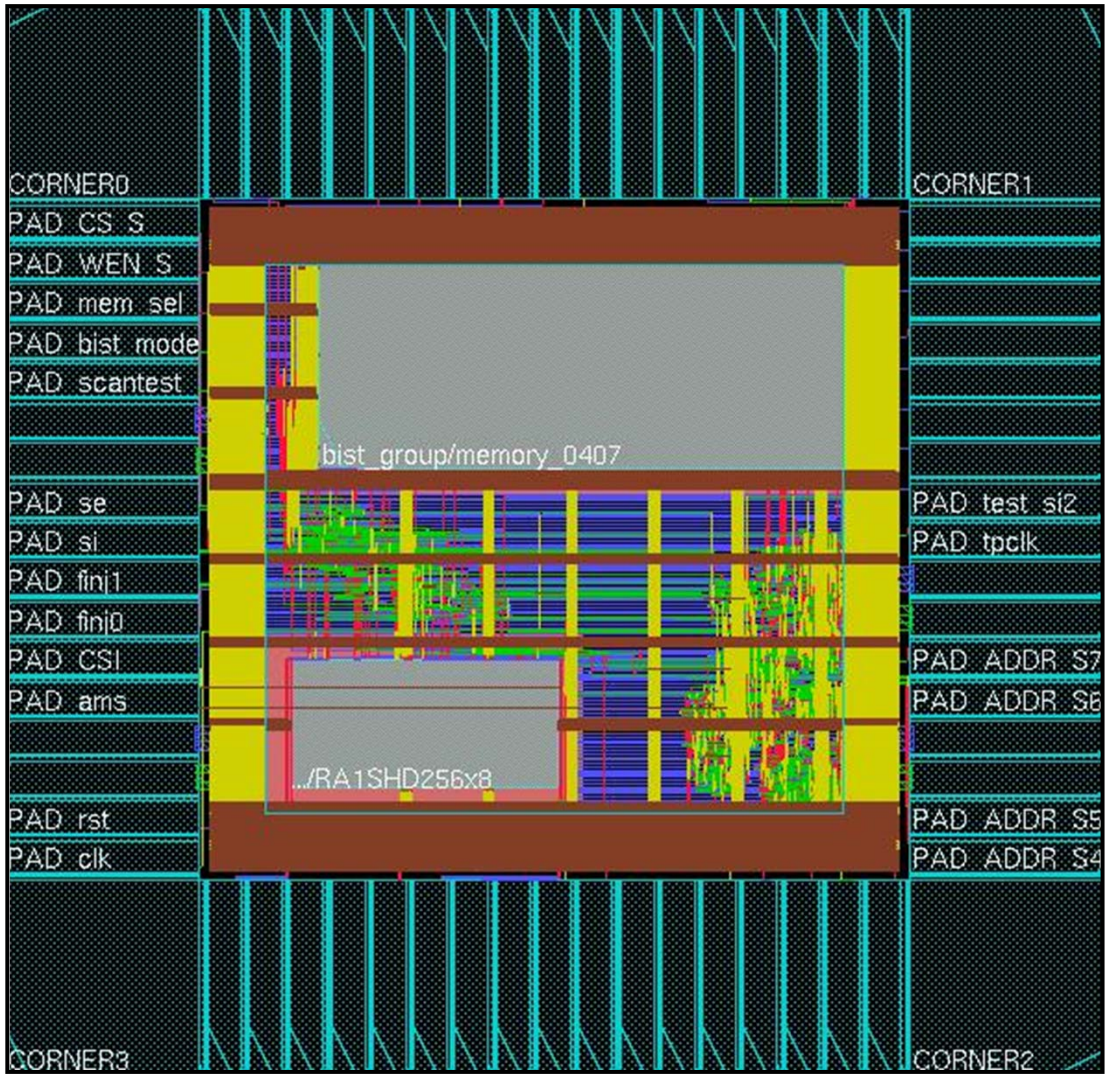
Nano Route

Route/NanoRoute



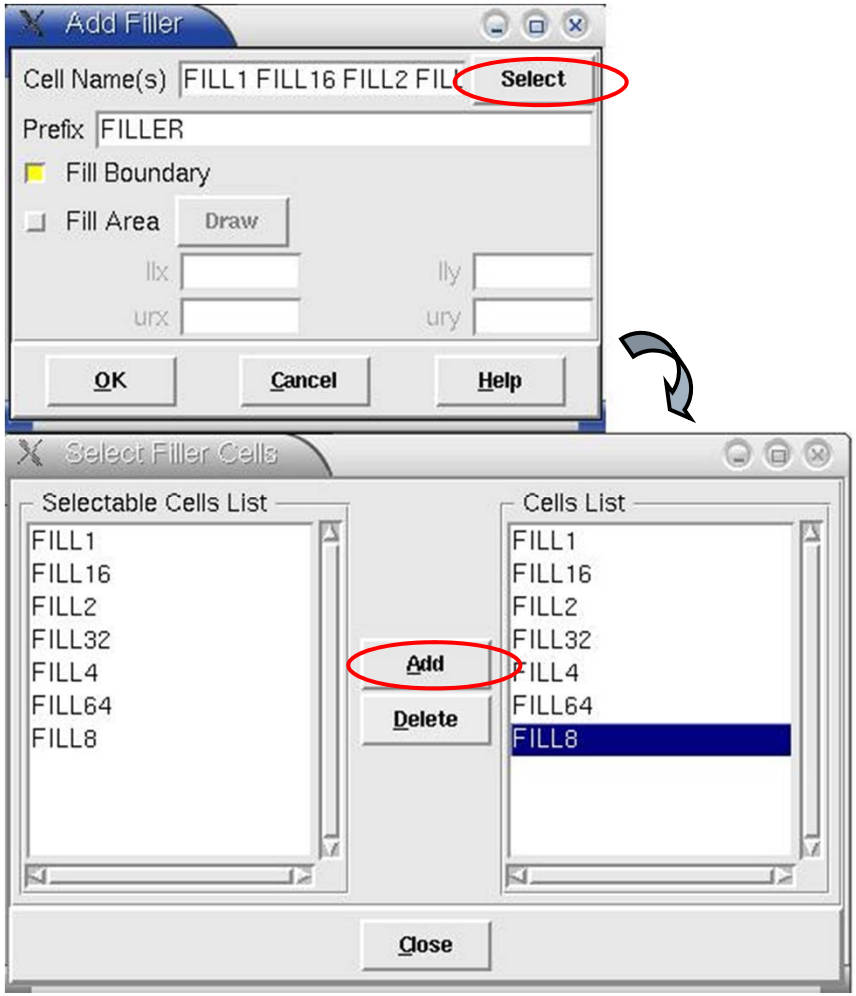


Example for Nano Route

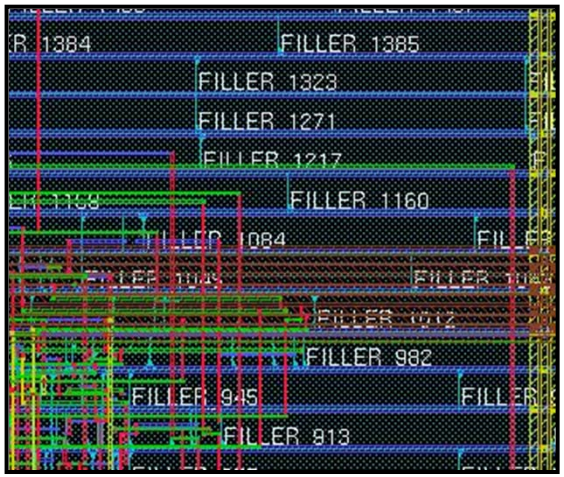


Cell Filler

- ***Place/Filler/Add Filler***



Ex:



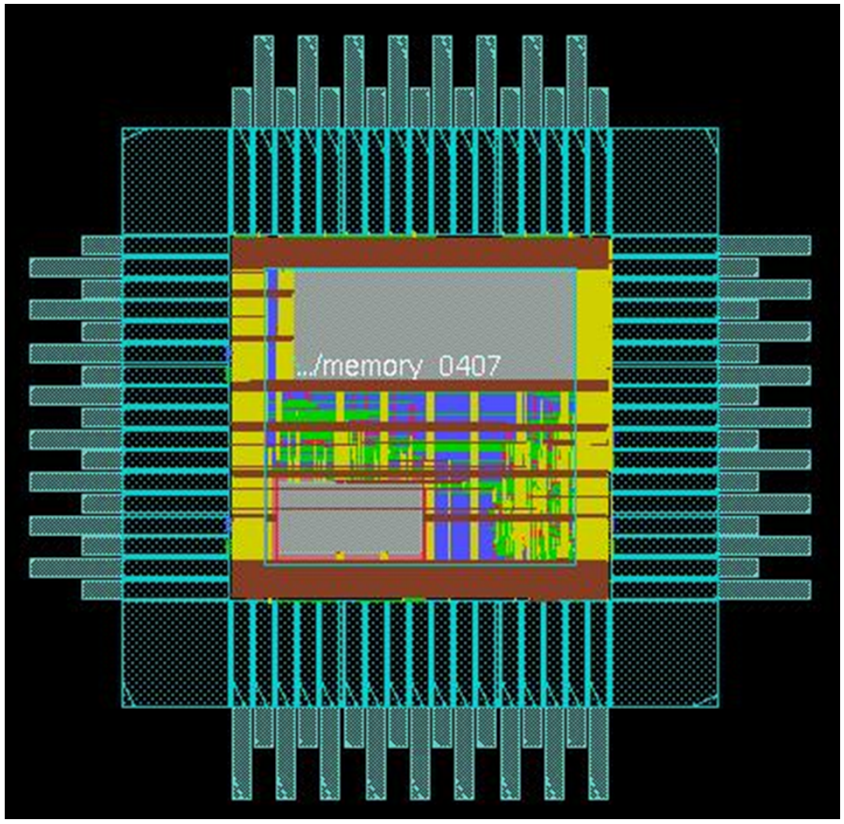
Save Design

- *Design/Save/Netlist → *.v*
- *Timing/Calculate Delay → *.sdf*
- *Design/Save/DEF → *.def*
  - *SELECT “Save Scan”*

Bounding PAD

- *unix %> chmod 755 addbonding.pl*
- *unix %> /usr/bin/perl addbonding.pl CHIP.def*
- *encounter %> source bondPads.cmd*

Ex:



Save GDSII

- *Design/Save/GDS → *.gds*

LAB

- 利用 SOC encounter 將 gate-level netlist 檔轉換為 layout 的 GDS 檔
- 實驗報告內容:
- 1.實驗目的
- 2.分別附上編輯完後的.vg檔.sdc檔.ioc檔
- 3.最後請附上.gds的結果,並確定無任何的violation。